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IBM PowerPC<sup>®</sup> 750FX RISC Microprocessor

**Datasheet**

**(Support for 750FX Design Revision Level DD 2.X)**

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Version: 2.0

**Preliminary**

June 9, 2003



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## 1. General Information

The IBM PowerPC® 750FX RISC Microprocessor is a 32-bit implementation of the IBM PowerPC family of reduced instruction set computer (RISC) microprocessors. This document contains pertinent physical and electrical characteristics of the IBM PowerPC 750FX RISC Microprocessor Revision DD 2.X Single Chip Modules (SCM). The IBM PowerPC 750FX RISC Microprocessor is also referred to as the 750FX throughout this document.

### 1.1 Features

This section summarizes the features of the 750FX implementation of the PowerPC Architecture™. Major features of the 750FX include the following:

- Branch processing unit
  - Four instructions fetched per clock
  - One branch processed per cycle (plus resolving two speculations)
  - Up to one speculative stream in execution, one additional speculative stream in fetch
  - 512-entry branch history table (BHT) for dynamic prediction
  - 64-entry, 4-way set associative branch target instruction cache (BTIC) for eliminating branch delay slots
- Decode
  - Register file access
  - Forwarding control
  - Partial instruction decode
- Load/store unit
  - One cycle load or store cache access (byte, half-word, word, double-word)
  - Effective address generation
  - Hits under miss (one outstanding miss)
  - Single-cycle misaligned access within double-word boundary
  - Alignment, zero padding, sign extend for integer register file
  - Floating-point internal format conversion (alignment, normalization)
  - Sequencing for load/store multiples and string operations
  - Store gathering
  - Cache and TLB instructions
  - Big and little-endian byte addressing supported
  - Misaligned little-endian support in hardware
- Dispatch unit
  - Full hardware detection of dependencies (resolved in the execution units)
  - Dispatch two instructions to six independent units (system, branch, load/store, fixed-point unit 1, fixed-point unit 2, or floating-point)
  - 4-stage pipeline: fetch, dispatch, execute, and complete
  - Serialization control (predispatch, postdispatch, execution, serialization)
- Fixed-point units
  - Fixed-point unit 1 (FXU1): multiply, divide, shift, rotate, arithmetic, logical
  - Fixed-point unit 2 (FXU2): shift, rotate, arithmetic, logical
  - Single-cycle arithmetic, shift, rotate, logical
  - Multiply and divide support (multi-cycle)
  - Early out multiply
  - Thirty-two 32-bit general purpose registers
- Floating-point unit
  - Support for IEEE-754 standard single and double-precision floating-point arithmetic
  - Optimized for single-precision multiply/add
  - Thirty-two, 64-bit floating point registers
  - Enhanced reciprocal estimates
  - 3-cycle latency, 1-cycle throughput, single-precision multiply-add
  - 3-cycle latency, 1-cycle throughput, double-precision add
  - 4-cycle latency, 2-cycle throughput, double-precision multiply-add
  - Hardware support for divide
  - Hardware support for denormalized numbers
  - Time deterministic non-IEEE mode
- System unit
  - Executes CR logical instructions and miscellaneous system instructions
  - Special register transfer instructions

- L1 Cache structure
  - 32K, 32-byte line, 8-way set associative instruction cache
  - 32K, 32-byte line, 8-way set associative data cache
  - Single-cycle cache access
  - Pseudo-LRU replacement
  - Copy-back or write-through data cache (on a page per page basis)
  - Parity on L1 tags and arrays
  - 3-state (MEI) memory coherency
  - Hardware support for data coherency
  - Non-blocking instruction cache (one outstanding miss)
  - Non-blocking data cache (two outstanding misses)
  - No snooping of instruction cache
- Memory management unit
  - 64 entry, 2-way set associative instruction TLB (total 128)
  - 64 entry, 2-way set associative data TLB (total 128)
  - Hardware reload for TLBs
  - 8 instruction BATs and 8 data BATs
  - Virtual memory support for up to 4 exabytes ( $2^{52}$ ) virtual memory
  - Real memory support for up to 4 gigabytes ( $2^{32}$ ) of physical memory
  - Support for big/little-endian addressing
- Dual PLLs
  - Allows seamless frequency switching
- Level 2 (L2) cache
  - Internal L2 cache controller and 4K-entry tags: 512KB data SRAMs
  - Two-way set-associative, supports locking by way
    - Copy-back or write-through data cache on a page basis, or for all L2
    - 64-byte sectored line size
    - L2 frequency at core speed
    - ECC protection on SRAM array
    - Parity on L2 tags
    - Supports up to 2 outstanding misses (1 data and 1 instruction or 2 data)
- Power
  - Low power consumption with low voltage application at lower frequency
  - Dynamic power management
  - 3 static power save modes (doze, nap, and sleep)
  - Thermal Assist Unit (TAU)
- Bus interface
  - 32-bit address bus
  - 64-bit data bus (also supports 32-bit mode)
  - Enhanced 60x bus: pipelines consecutive reads to a depth of 2
  - Core-to-bus frequency multipliers of 3.5x, 4x, 4.5x, 5x, 5.5x, 6x, 6.5x, 7x, 7.5x, 8x, 8.5x, 9x, 9.5x, 10x, 11x, 12x, 13x, 14x, 15x, 16x, 17x, 18x, 19x, and 20x supported
  - Supports 1.8V, 2.5V, or 3.3V I/O modes
- Reliability and serviceability
  - Parity checking on 60x interface
  - ECC checking on L2 cache
  - Parity on the L1 arrays
  - Parity on the L1 and L2 tags
- Testability
  - LSSD scan design
  - Powerful diagnostic and test interface through Common On-Chip Processor (COP) and IEEE 1149.1 (JTAG) interface

## 1.2 Design Level Considerations and Features

The 750FX supports several unique features including those listed below. The IBM application note *Differences between the PowerPC 750FX, 750, 750CX, and 750CXe Microprocessors* provides a more detailed explanation of these features.

- Incorporates an on-chip, 512K, two-way, set-associative L2 cache
- Provides a 64 or 32-bit Data Bus mode (per setup of  $\overline{\text{TLBISYNC}}$  pin)
- Supports 1.8V, 2.5V, or 3.3V I/O modes

**Implementation Note:** DD2.0 supports a limited use of the 3.3V I/O mode. For additional information, see the *750FX Errata List of Revision DD2.X*.

- Includes all 60x bus pins on earlier PowerPC 750 designs and additional signals
- Enhanced 60x bus — for pipelined consecutive read transactions and higher frequency operation
- Dual PLLs for additional power savings capabilities
- Four additional IBAT/DBAT registers
- New CBGA package with additional pins and depopulated footprint

## 1.3 Processor Version Register

The PowerPC 750FX RISC Microprocessor has the following Processor Version Register (PVR) values for the respective design revision levels.

The 750FX PVR is 7000, which is not used in any previous PowerPC processor design.

Table 1-1. 750FX Processor Version Register (PVR)

750FX Design Revision Level	750FX PVR
DD2.0	0x700a02b0
DD2.1	0x700a02b1
DD2.2	0x700a02b2
DD2.3	0x700a02b3

**Note:**

1. Nibbles shown as 'b' are to be ignored, and are for factory use only. Nibbles shown as 'a' may be 0 or 1
2. If L2\_TSTCLK is pulled low, the PVR may read 0x000802b\_. L2TSTCLK should be pulled up for normal operation.

## 1.4 Part Number Information

Figure 1-1. Part Number Legend

# IBM25PPC750FX-GByy x3T

Process Technology	"—" = 0.13 μm CSOI
Design Revision Level	D = DD2.0 E = DD2.1 F = DD2.2 G = DD2.3
Package Type	B = Ceramic Ball Grid Array
Performance Sort	01 = Nominal at 600 MHz 05 = Nominal at 700 MHz 10 = Nominal at 733 MHz 25 = Nominal at 800 MHz
Test Conditions	1 = (see Datasheet Supplement and PCN-IBM-050803 2 = Special Test Conditions 3 = 1.4 - 1.5V @ 105°C
Reliability Grade	3 = Grade 3, <100 FIT AFR 2 = Grade 2, < 25 FIT AFR
Shipping Container	T = Tray

**Note:** See the Datasheet Supplement for additional application conditions.



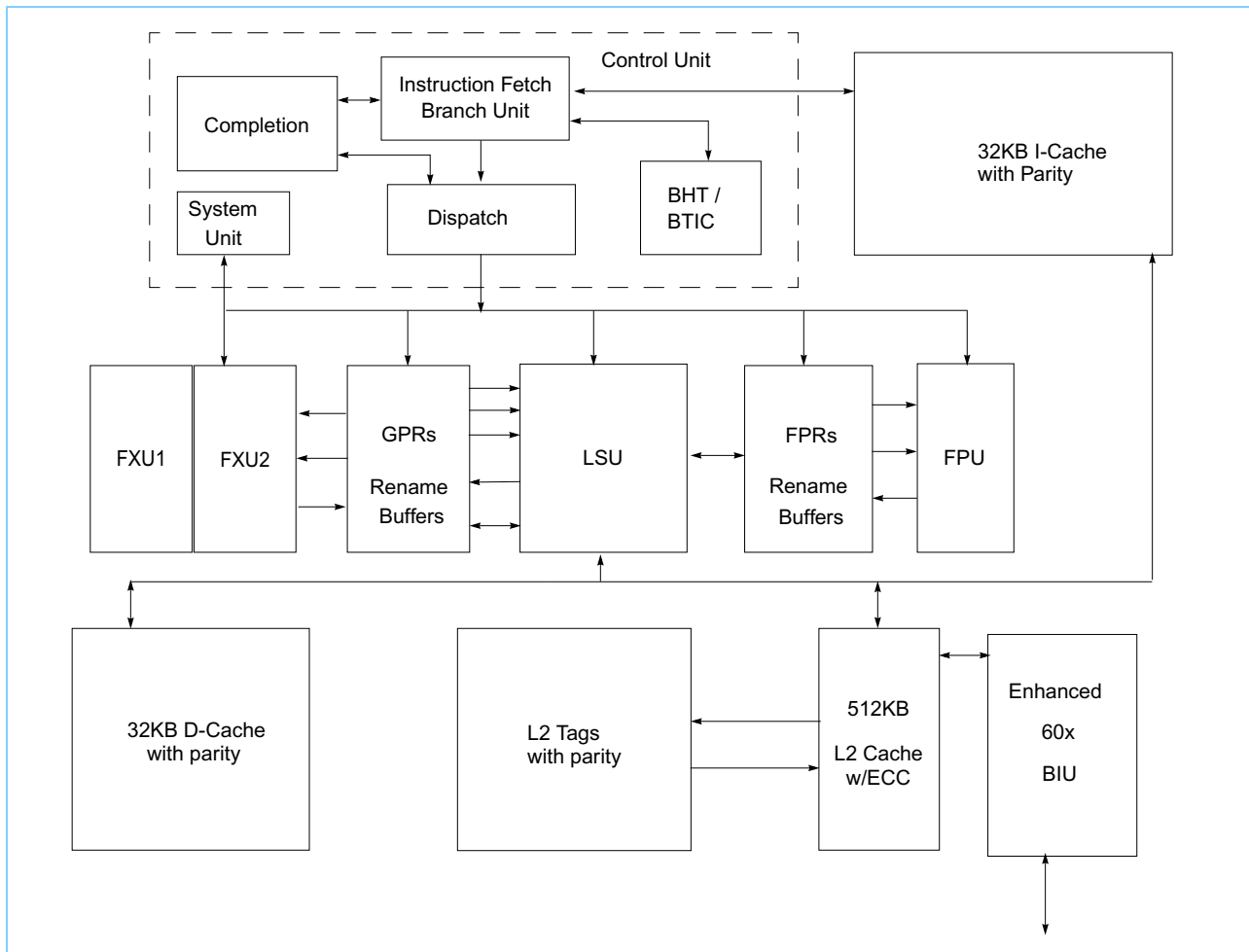
## 2. Overview

The PowerPC 750FX RISC Microprocessor, also called the 750FX, is targeted for high performance, low power systems using a 60x bus. The 750FX also includes an internal 512KB L2 cache with on-board Error Correction Circuitry (ECC).

### 2.1 Block Diagram

Figure 2-1 shows a block diagram of the PowerPC 750FX RISC Microprocessor.

Figure 2-1. PowerPC 750FX RISC Microprocessor Block Diagram



## 2.2 General Parameters

Table 2-1 provides a summary of the general parameters of the 750FX.

Table 2-1. 750FX General Parameters

Item	Description	Notes
Technology	0.13µm CSOI technology, six-layer metallization plus one level of local interconnect	
Die Size	34.3 sq. mm	
Transistor count	38 million - including L2 cache	
Logic design	Fully-static	
Package	292-pin ceramic ball grid array (CBGA) 21x21mm (1.0 mm pitch) 0.8 mm ball size	
Core power supply	1.45V +/- 50 mV	1
I/O power supply	3.3V +/- 165mV (BVSEL = 1, L1_TSTCLK = 0) or 2.5V +/- 125mV (BVSEL = 1, L1_TSTCLK = 1) or 1.8V +/- 100mV (BVSEL = 0, L1_TSTCLK = 1)	2

**Note:**

1. In some cases, when using 1.8v or 2.5v IO mode, it is possible to reduce power dissipation by lowering the core power supply voltage. See the Datasheet Supplement for details.
2. BVSEL =0, L1\_TSTCLK = 0 is an INVALID setting. DD2.0 supports only a limited use of 3.3v IO mode. See the 750FX Errata List for revision DD2.x for more information.

### 3. Electrical and Thermal Characteristics

This section provides AC and DC electrical specifications and thermal characteristics for the 750FX.

#### 3.1 DC Electrical Characteristics

The tables in this section describe the DC electrical characteristics for the 750FX.

Table 3-1. Absolute Maximum Ratings<sup>1</sup>

Characteristic	Symbol	1.8V	2.5V	3.3V	Unit	Notes
Core supply voltage	$V_{DD}$	-0.3 to 1.6	-0.3 to 1.6	-0.3 to 1.6	V	3, 4
PLL supply voltage	$A1V_{DD}$ , $A2V_{DD}$	-0.3 to 1.6	-0.3 to 1.6	-0.3 to 1.6	V	3, 4, 5
60x bus supply voltage	$OV_{DD}$	-0.3 to 2.0	-0.3 to 2.75	-0.3 to 3.7	V	3, 4
Input voltage	$V_{IN}$	-0.3 to 2.0	-0.3 to 2.75	-0.3 to 3.7	V	2
Storage temperature range	$T_{STG}$	-55 to 150	-55 to 150	-55 to 150	°C	

**Notes:**

1. Functional and tested operating conditions are given in Table 3-2, "Recommended Operating Conditions" on page 10. Absolute maximum ratings are stress ratings only, and functional operation at the maximums is not guaranteed. Stresses beyond those listed above may affect device reliability or cause permanent damage to the device.
2. **Caution:** Transient  $V_{IN}$  overshoots of up to  $OV_{DD} + 0.8V$ , with a maximum of 4.0V for 3.3V operation, and undershoots down to  $GND - 0.8V$ , are allowed for up to 5ns.
3. **Caution:**  $OV_{DD}$  must not exceed  $V_{DD}/AV_{DD}$  by more than 2.1V continuously.  $OV_{DD}$  may exceed  $V_{DD}/AV_{DD}$  by up to 2.3V for up to 20ms during power-on or power-off.  $OV_{DD}$  must not exceed  $V_{DD}/AV_{DD}$  by more than 2.3V for any amount of time.
4. **Caution:**  $V_{DD}/AV_{DD}$  must not exceed  $OV_{DD}$  by more than 1.0V continuously.  $V_{DD}/AV_{DD}$  may exceed  $OV_{DD}$  by up to 1.6v for up to 20ms during power-on or power-off.  $V_{DD}/AV_{DD}$  must not exceed  $OV_{DD}$  by more than 1.6V for any amount of time.
5. **Caution:**  $AV_{DD}$  must not exceed  $V_{DD}$  by more than 0.5V at any time.

**Note:** All electrical specifications (AC, DC, timing) are guaranteed only while the device is operated within the recommended operating conditions (see *Table 3-2*). Operation at other application conditions may also be possible; see the PowerPC 750FX RISC Microprocessor Datasheet Supplement for details.

*Table 3-2. Recommended Operating Conditions*

Characteristic	Symbol	Value	Unit	Notes
Core supply voltage (full-on mode)	$V_{DD}$	1.4 to 1.5	V	1, 2
Low Voltage (Low Frequency Operation, 1.8V and 2.5V bus modes only)	$V_{DD}$	1.2 Minimum	V	1
PLL supply voltage	$AV_{DD}$	1.4 to 1.5	V	2
60x bus supply voltage (1.8V)	$OV_{DD}$	1.7 to 1.9	V	2
60x bus supply voltage (2.5V)	$OV_{DD}$	2.375 to 2.625	V	2
60x bus supply voltage (3.3V)	$OV_{DD}$	3.135 to 3.465	V	
Input voltage	$V_{IN}$	GND to $OV_{DD}$	V	2
Die-junction temperature DD2.0 and 2.1	$T_J$	0 to 105	°C	
Die-junction temperature DD2.2 and 2.3	$T_J$	-40 to 105		

**Notes:**

1. In some cases, when using 1.8v or 2.5v IO mode, it is possible to reduce power dissipation by lowering the core power supply voltage. See the Datasheet Supplement for details.
2. These are tested operating conditions.

*Table 3-3. Package Thermal Characteristics<sup>1</sup>*

Characteristic	Symbol <sup>2</sup>	Value	Unit
CBGA package thermal resistance, junction-to-case thermal resistance (typical)	$\theta_{JC}$	0.06	°C/W
CBGA package thermal resistance, junction-to-lead thermal resistance (typical)	$\theta_{JB}$	7.6	°C/W

**Notes:**

1. A heat sink is required (see *Section 5.8 Thermal Management* on page 49).
2.  $\theta_{JC}$  is the internal resistance from the junction to the back of the die. For more information about thermal management, see *Section 5.8 Thermal Management* on page 49.

**Table 3-4. DC Electrical Specifications**

See Table 3-2 on page 10 for recommended operating conditions.

Characteristic	Symbol	Voltage		Unit	Notes
		Min	Max		
Input high voltage (all inputs except SYSCLK)	$V_{IH(1.8V)}$	1.20		V	
	$V_{IH(2.5V)}$	1.70		V	
	$V_{IH(3.3V)}$	2.1		V	
Input low voltage (all inputs except SYSCLK)	$V_{IL(1.8V)}$		0.60	V	
	$V_{IL(2.5V)}$		0.70	V	
	$V_{IL(3.3V)}$		0.80	V	
SYSCLK input high voltage	$CV_{IH(1.8V)}$	1.20		V	
	$CV_{IH(2.5V)}$	1.90		V	
	$CV_{IH(3.3V)}$	2.1		V	
SYSCLK input low voltage	$CV_{IL(1.8V)}$		0.40	V	
Input leakage current, $V_{IN}$ = applies to all $OV_{DD}$ levels	$I_{IN}$		20	$\mu A$	2
Hi-Z (off state) leakage current, $V_{IN}$ = applies to all $OV_{DD}$ levels	$I_{TSI}$		20	$\mu A$	2
Output high voltage, $I_{OH} = -4mA$	$V_{OH(1.8V)}$	1.30		V	
	$V_{OH(2.5V)}$	2.00		V	
	$V_{OH(3.3V)}$	2.40		V	
Output low voltage, $I_{OL} = 4mA$	$V_{OL(1.8V, 2.5V, 3.3V)}$		0.4	V	
Capacitance, $V_{IN} = 0V$ , $f = 1MHz$	$C_{IN}$		5	pF	1

**Notes:**

1. Capacitance values are guaranteed by design and characterization, and are not tested.
2. Additional input current may be attributed to the Level Protection Keeper Lock circuitry. For details, see *Section 5.5 Level Protection* on page 48.

**Table 3-5. Power Consumption**  
 See Table 3-2 on page 10 for recommended operating conditions.

Mode	V <sub>DD</sub>	T <sub>j</sub>	Representative Processor Frequency (see note 6)					Unit	Notes
			400 MHz	600 MHz	700 MHz	733 MHz	800 MHz		
Full-On Mode									
Maximum	1.45V	105°C	7.1	7.9	8.2	8.3	8.6		1, 2
	1.5V	105°C	7.9	8.7	9.3	9.4	9.7		1, 2
Typical	1.45V	85°C	3.9	4.6	5.0	5.1	5.4		1, 3
Nap Mode									
Typical	1.45V	50°C	1.4	1.5	1.6	1.6	1.6	W	1
Sleep Mode									
Typical	1.45V	50°C	1.4	1.4	1.4	1.4	1.4	W	1
<b>Notes:</b>									
1. These values apply for all valid 60x buses. The values do not include I/O Supply Power (OV <sub>DD</sub> ) or PLL/DLL supply power (AV <sub>DD</sub> ). OV <sub>DD</sub> power is system dependent, but is typically <2% of V <sub>DD</sub> power. AV <sub>DD</sub> current is less than 25mA each for AV <sub>DD1</sub> and AV <sub>DD2</sub> . 2. Maximum power is specified for fastest (worst process) parts running RC5 at the indicated core voltage, junction temperature, and core frequency. 3. Typical power is specified for median process 800 MHz parts0 running RC5 at the indicated core voltage, junction temperature, and core frequency. The value is then adjusted for 13% less switching (AC component for P <sub>D</sub> ) to account for the differences between RC5 and more typical application code.									

Previous revisions of this datasheet showed incorrectly low power dissipation values. The power dissipation of the 750FX has not increased, the datasheet has only been corrected to show the actual values.

### 3.2 Clock AC Specifications

Table 3-6 provides the clock AC timing specifications as defined in Figure 3-1.

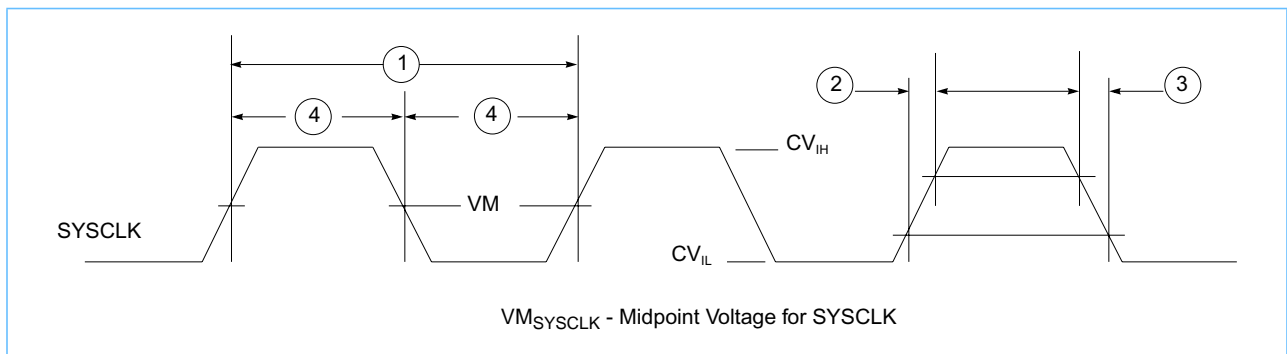
Table 3-6. Clock AC Timing Specifications (See Table 3-2 on page 10 for recommended operating conditions<sup>1,6</sup>)

Num (Timing Reference)	Characteristic	Value		Unit	Notes
		Min.	Max.		
	Processor frequency	400	800	MHz	7
	SYSCLK frequency	20	200	MHz	1, 6
1	SYSCLK cycle time	5.0	50	ns	
2, 3	SYSCLK rise and fall slew rate	1.0	—	V/ns	3
4	SYSCLK duty cycle measured at 0.8V	25	75	%	3
VM <sub>SYSCLK</sub>	Measurement Reference Voltage for SYSCLK (all I/O voltages)	0.65		V	
	SYSCLK cycle-to-cycle jitter	—	±150	ps	4, 3
	Internal PLL relock time	—	100	μs	5

**Notes:**

- Caution:** The SYSCLK frequency and the PLL\_CFG[0:4] settings must be chosen such that the resulting SYSCLK (bus) frequency, CPU (core) frequency, and PLL frequency do not exceed their respective maximum or minimum operating frequencies. Refer to the PLL\_CFG[0:4] signal description in Table 5-2, "750FX Microprocessor PLL Configuration" on page 33 for valid PLL\_CFG[0:4] settings.
- The SYSCLK slew rate applies between 0.4V and 1.0V.
- Timing is guaranteed by design and characterization, and is not tested.
- See Section 3.3 Spread Spectrum Clock Generator (SSCG) on page 14 for long term jitter.
- Relock timing is guaranteed by design and characterization, and is not tested. PLL-relock time is the maximum amount of time required for PLL lock after a stable V<sub>DD</sub> and SYSCLK are reached during the power-on reset sequence. This specification also applies when the PLL has been disabled and subsequently re-enabled during sleep mode. Also note that HRESET must be held asserted for a minimum of 255 bus clocks after the PLL-relock time during the power-on reset sequence.
- This is a statement of the capability of the 750FX I/O circuitry. Not all systems can run at the maximum SYSCLK frequency. Contact IBM PowerPC Application Engineering for more information on high-speed bus design.
- Lower voltage/frequency operation: For additional information, see 750FX Datasheet Supplement for DD2.X Revisions.

Figure 3-1. SYSCLK Input Timing Diagram



### 3.3 Spread Spectrum Clock Generator (SSCG)

When designing with the SSCG, there are a number of design issues that must be taken into account.

SSCG creates a controlled amount of long-term jitter. In order for a receiving PLL in the 750FX to operate in this environment, it must be able to accurately track the SSCG clock jitter.

The accuracy to which the 750FX PLL can track the SSCG clock is referred to as tracking skew. When performing system timing analysis, the tracking skew must be added or subtracted to the I/O timing specifications because the tracking skew appears as a static phase error between the internal PLL and the SSCG clock.

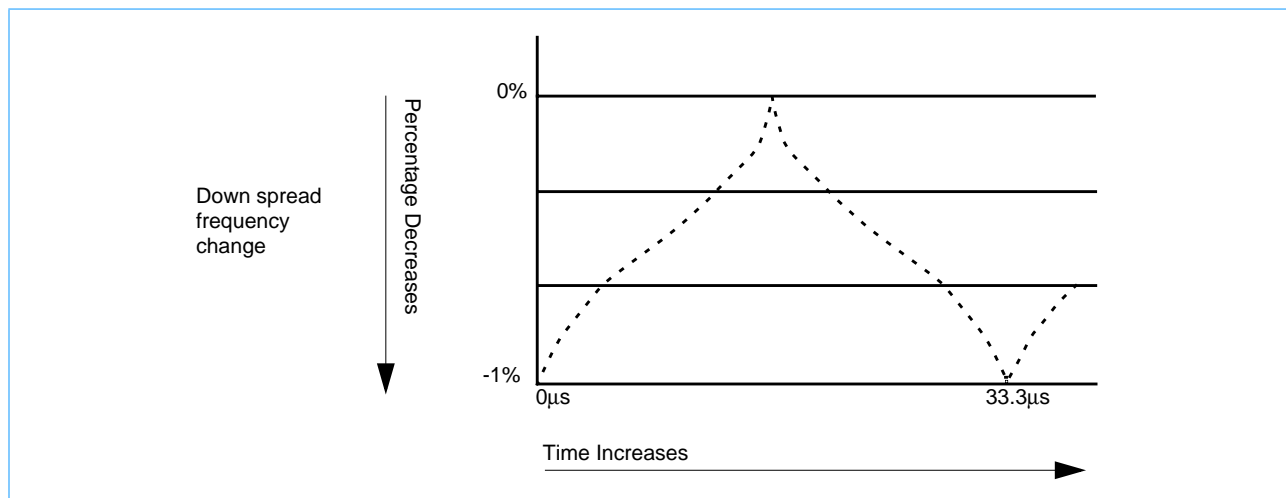
To minimize the impact on I/O timings the following SSCG configuration is recommended:

The following SSCG configuration is recommended:

- - Down spread mode, less than or equal to 1% of the maximum frequency
- - A modulation frequency of 30kHz
- - Linear sweep modulation or “Hershey Kiss™1” (as in a Lexmark2 profile) modulation profile as shown in *Figure 3-2* on page 14.

In this configuration the tracking skew is less than 100ps.

*Figure 3-2. Linear Sweep Modulation Profile*



1. Hershey Kiss is a trademark of Hershey Foods Corporation.  
2. See patent 5,631,920.



### 3.4 60x Bus Input AC Specifications

Table 3-7. 60x Bus Input Timing Specifications  
See Table 3-2 on page 10 for operating conditions.<sup>1,5</sup>

Num	Characteristic	1.8V Mode		2.5V Mode		3.3V Mode		Unit	Notes
		Min.	Max.	Min.	Max.	Min.	Max.		
10a	All inputs valid to SYSCLK (input setup)	1.0	—	1.5	—	1.8	—	ns	—
10b	$\overline{INT\_}$ , $\overline{SMI\_}$ , MCP, TBEN, DRTRY, and TLBISYNC (input setup)	1.5	—	1.5	—	1.8	—		
10c	Mode select input setup to $\overline{HRESET}$ (TLBISYNC, DRTRY)	8	—	8	—	8	—	$t_{SYSCLK}$	2, 3, 4, 5
11a	SYSCLK to inputs invalid (input hold)	0.65	—	0.65	—	0.55	—	ns	6
11b	$\overline{INT\_}$ , $\overline{SMI\_}$ , MCP, TBEN, DRTRY, and TLBISYNC (input hold)	1.5	—	2.5	—	2.5	—	ns	
11c	$\overline{HRESET}$ to mode select input hold (TLBISYNC, DRTRY)	0	—	0	—	0	—	ns	2, 4, 5
VM	Measurement Reference Voltage for Inputs	OV <sub>DD</sub> /2						—	—

**Notes:**

1. Input specifications are measured from the VM of the signal in question to VM of the rising edge of the input SYSCLK. Input and output timings are measured at the pin (see Figure 3-3).
2. The setup and hold time is with respect to the rising edge of  $\overline{HRESET}$  (see Figure 3-4 on page 16).
3.  $t_{SYSCLK}$  is the period of the external clock (SYSCLK) in nanoseconds (ns). The numbers given in the table must be multiplied by the period of SYSCLK to compute the actual time duration (in ns) of the parameter in question.
4. This specification is for configuration mode select only. Also note that the  $\overline{HRESET}$  must be held asserted for a **minimum of 255 bus clocks** after the PLL relock time during the power-on reset sequence.
5. All values are guaranteed by design, and are not tested.
6. See *Alternate I/O Timing For 3.3V Bus* on page 19

Figure 3-3 provides the input timing diagram for the 750FX.

Figure 3-3. Input Timing Diagram

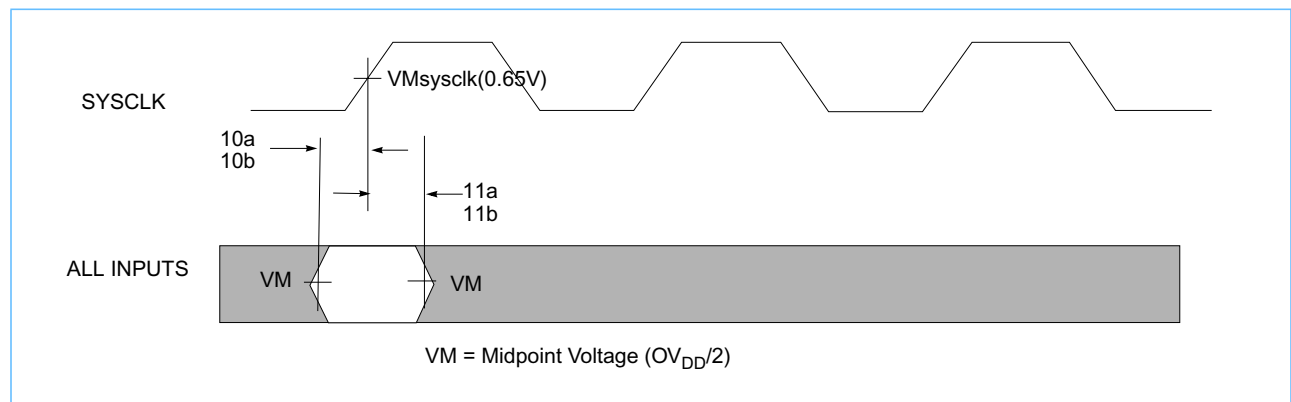
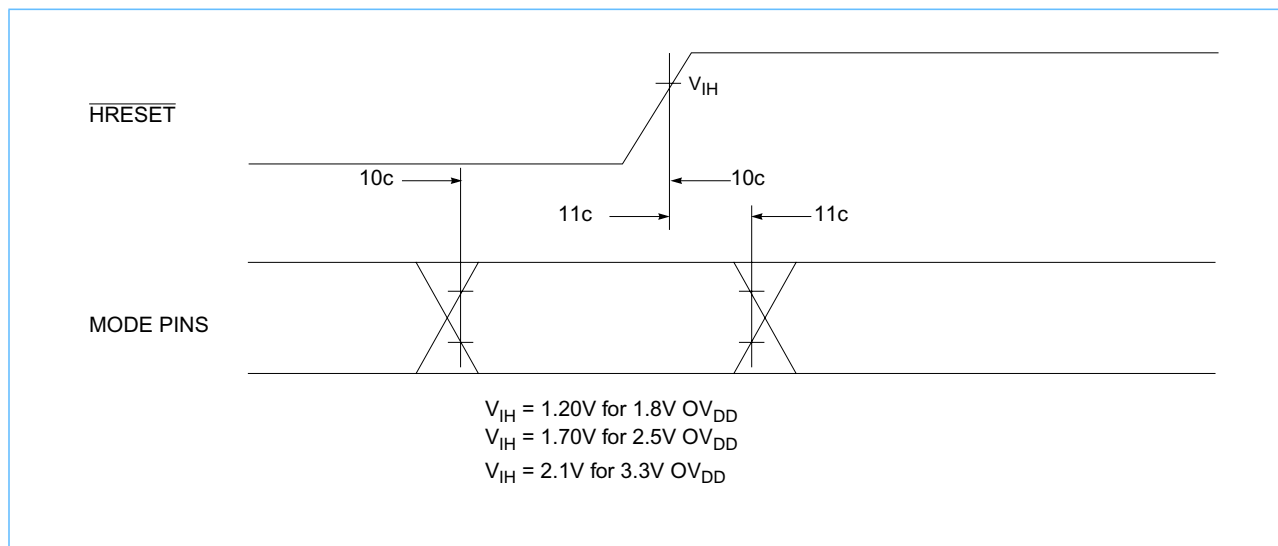


Figure 3-4 provides the mode select input timing diagram for the 750FX.

Figure 3-4. Mode Select Input Timing Diagram



### 3.5 60x Bus Output AC Specifications

Table 3-8 provides the 60x bus output AC timing specifications for the 750FX as defined in Figure 3-6 on page 19.

*Table 3-8. 60x Bus Output AC Timing Specifications*  
See Table 3-2 on page 10 for operating conditions.<sup>1, 5</sup>

Num	Characteristic	1.8V		2.5V		3.3V		Unit	Notes
		Min.	Max.	Min.	Max.	Min.	Max.		
12	SYSCLK to Output Driven (Output Enable Time)	0.3	—	0.3	—	0.3	—	ns	—
13	SYSCLK to Output Valid	—	2.3	—	2.5	—	2.5	ns	2, 6
14	SYSCLK to Output Invalid (Output Hold)	0.5	—	0.55	—	0.55	—	ns	2, 7
15	SYSCLK to Output High Impedance (all signals except $\overline{\text{ARTRY}}$ , $\overline{\text{ABB}}$ and $\overline{\text{DBB}}$ )	—	2.5	—	2.5	—	2.5	ns	—
16	SYSCLK to $\overline{\text{ABB}}$ and $\overline{\text{DBB}}$ high impedance after precharge	—	1.0	—	1.0	—	1.0	$t_{\text{SYSCLK}}$	3, 4
17	SYSCLK to $\overline{\text{ARTRY}}$ high impedance before precharge	—	3.0	—	3.0	—	3.0	ns	—
18	SYSCLK to $\overline{\text{ARTRY}}$ precharge enable	$0.2 \times t_{\text{SYSCLK}} + 1.0$	—	$0.2 \times t_{\text{SYSCLK}} + 1.0$	—	$0.2 \times t_{\text{SYSCLK}} + 1.0$	—	ns	2, 3, 4
19	Maximum delay to $\overline{\text{ARTRY}}$ precharge	—	1.0	—	1.0	—	1.0	$t_{\text{SYSCLK}}$	3, 4
20	SYSCLK to $\overline{\text{ARTRY}}$ high impedance after precharge	—	2.0	—	2.0	—	2.0	$t_{\text{SYSCLK}}$	3, 4

**Notes:**

1. All output specifications are measured from the VM of the rising edge of SYSCLK to the output signal level defined in Figure 3-5 on page 18. Both input and output timings are measured at the pin. Timings are determined by design.
2. This minimum parameter assumes  $C_L = 0\text{pF}$ .
3.  $t_{\text{SYSCLK}}$  is the period of the external bus clock (SYSCLK) in nanoseconds (ns). The numbers given in the table must be multiplied by the period of SYSCLK to compute the actual time duration of the parameter in question.
4. Nominal precharge width for  $\overline{\text{ARTRY}}$  is  $1.0 t_{\text{SYSCLK}}$ .
5. Guaranteed by design and characterization, and not tested.
6. Output Valid timing increases as the  $V_{\text{DD}}$  is reduced. These values assume  $V_{\text{DD}}$  minimum of 1.35V.
7. See *Alternate I/O Timing For 3.3V Bus* on page 19

Figure 3-5. Output Valid Timing Definition

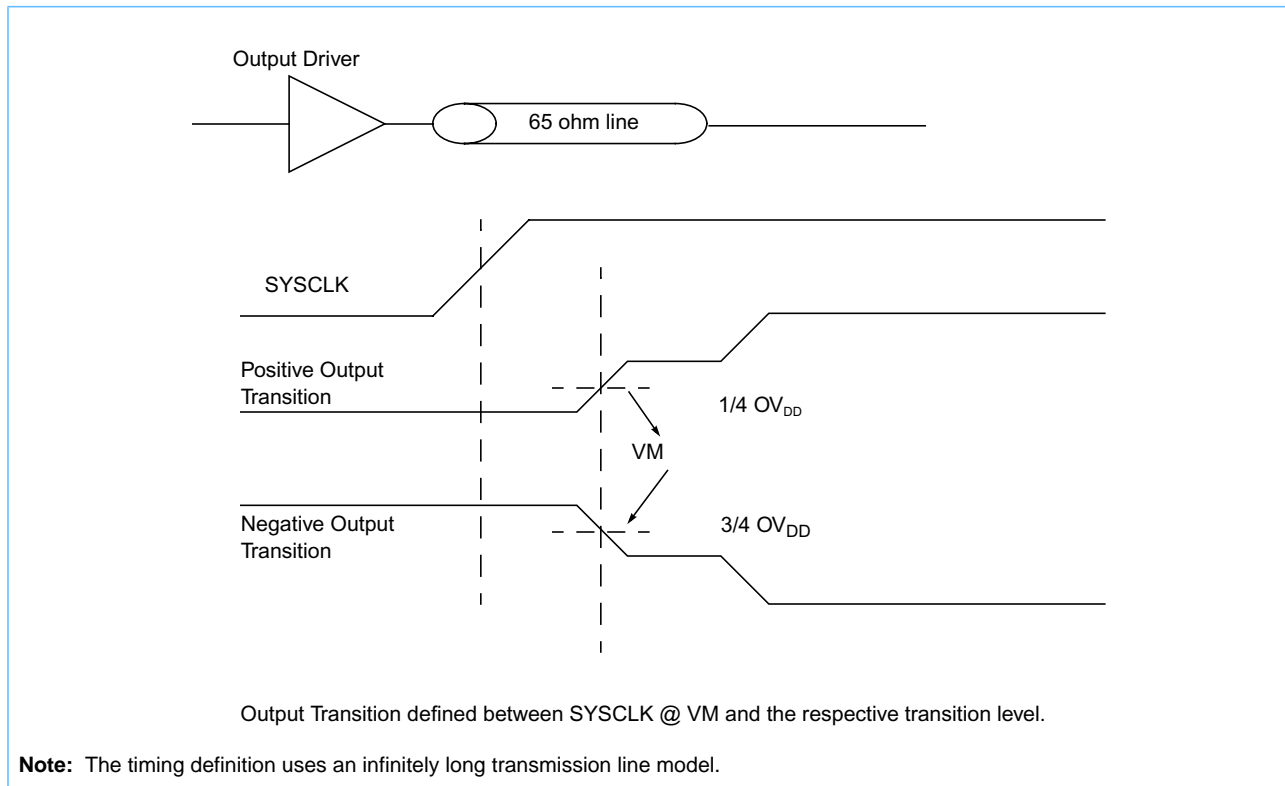
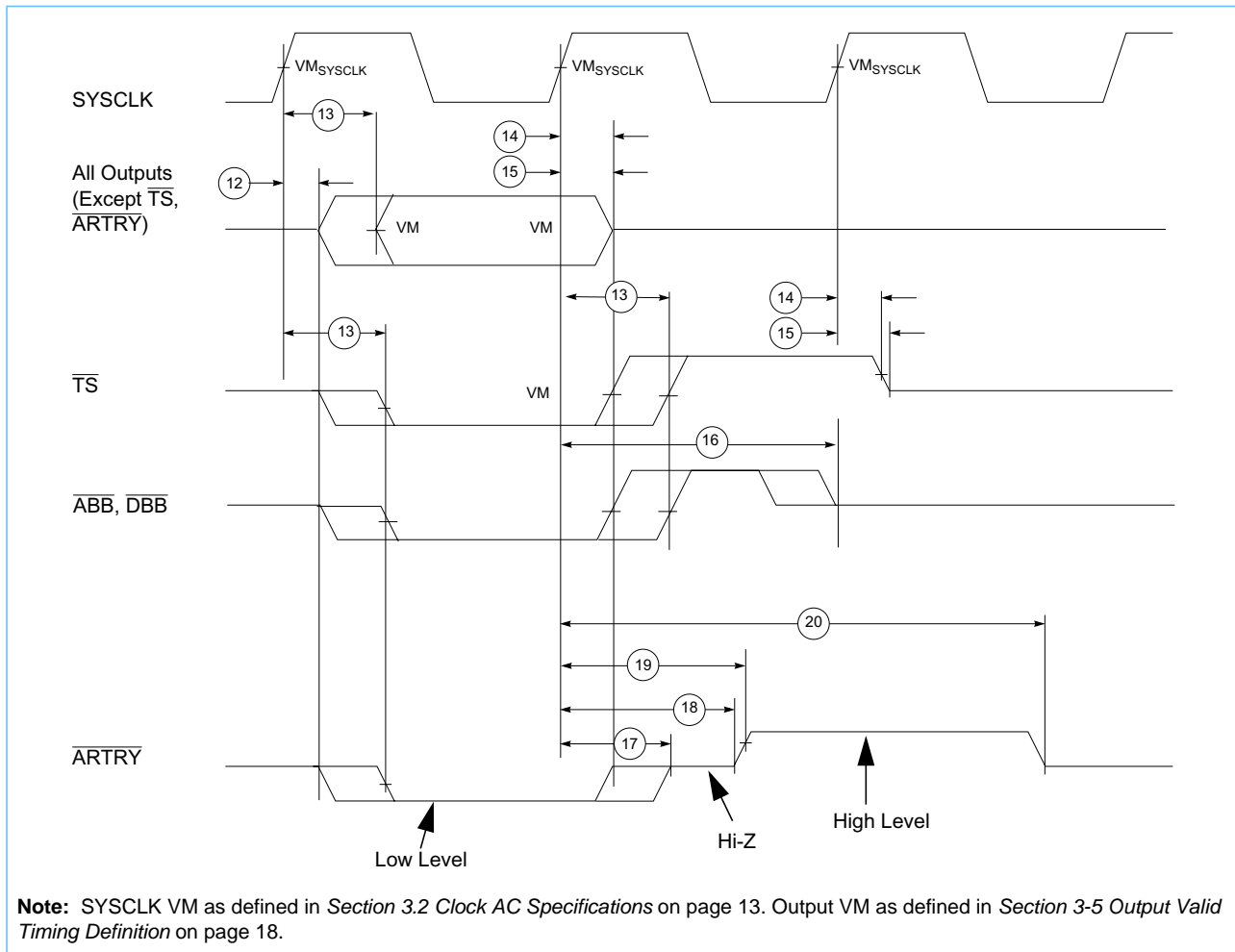


Figure 3-6. Output Timing Diagram for PowerPC 750FX RISC Microprocessor



### 3.6 Alternate I/O Timing For 3.3V Bus

An alternate I/O timing specification may be used for dd2.3, where:

- $OV_{DD} = 3.3V \pm 5\%$ ,
- $V_{DD} = 1.45V \pm 50mV$ , and
- $T_j = -40^{\circ}C$  to  $105^{\circ}C$ .
- All other recommended operating conditions are as per Table 3-2.

The following alternate I/O timing specifications may be used under the above conditions:

1. Consider  $V_M = 1/2 (OV_{DD})$  for SYSCLK, input timing, and output timings.
2. Input hold (T11a) becomes 250 ns minimum for 3.3V. Output hold (T14) becomes 650 ns minimum for 3.3V.
3. All other timing specifications are unchanged.

### 3.6.1 IEEE 1149.1 AC Timing Specifications

The five JTAG signals are; TDI, TDO, TMS, TCK, and  $\overline{\text{TRST}}$ . Unless otherwise noted, JTAG specifications are referenced to GND and  $\text{OV}_{\text{DD}}$ . The JTAG I/Os are powered by  $\text{OV}_{\text{DD}}$ .

Table 3-9. JTAG AC Timing Specifications (Independent of SYSCLK)

See Table 3-2 on page 10 for operating conditions.

Num	Characteristic	Min.	Max.	Unit	Notes
	TCK frequency of operation	0	25	MHz	
1	TCK cycle time	40	—	ns	
2	TCK clock pulse width measured at 1.1V	15	—	ns	
3	TCK rise and fall times	0	2	ns	4
4	Specification obsolete, intentionally omitted				
5	$\overline{\text{TRST}}$ assert time	25	—	ns	1
6	Boundary-scan input data setup time	0	—	ns	2
7	Boundary-scan input data hold time	13	—	ns	2
8	TCK to output data valid	—	8	ns	3, 5
9	TCK to output high impedance	3	19	ns	3, 4
10	TMS, TDI data setup time	0	—	ns	
11	TMS, TDI data hold time	15	—	ns	
12	TCK to TDO data valid	2.0	12	ns	5
13	TCK to TDO high impedance	3	9	ns	4
14	TCK to output data invalid (output hold)	0	—	ns	

**Notes:**

1.  $\overline{\text{TRST}}$  is an asynchronous level sensitive signal. Guaranteed by design.
2. Non-JTAG signal input timing with respect to TCK.
3. Non-JTAG signal output timing with respect to TCK.
4. Guaranteed by characterization and not tested.
5. Minimum specification guaranteed by characterization and not tested.

Figure 3-7. JTAG Clock Input Timing Diagram

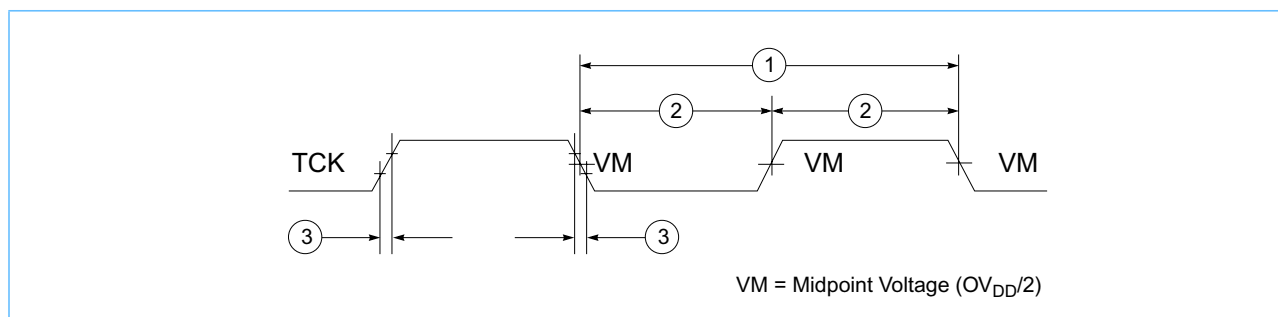


Figure 3-8.  $\overline{TRST}$  Timing Diagram

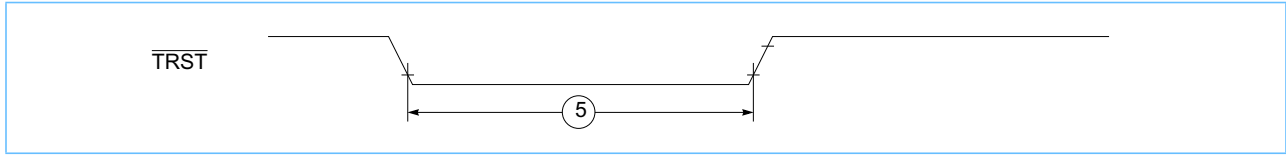


Figure 3-9. Boundary-Scan Timing Diagram

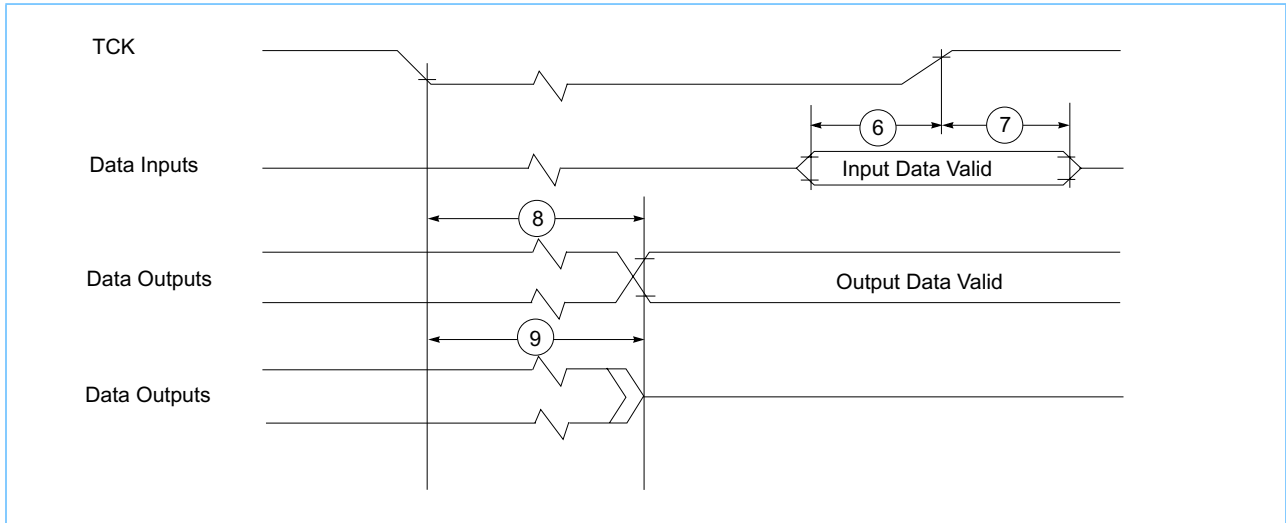
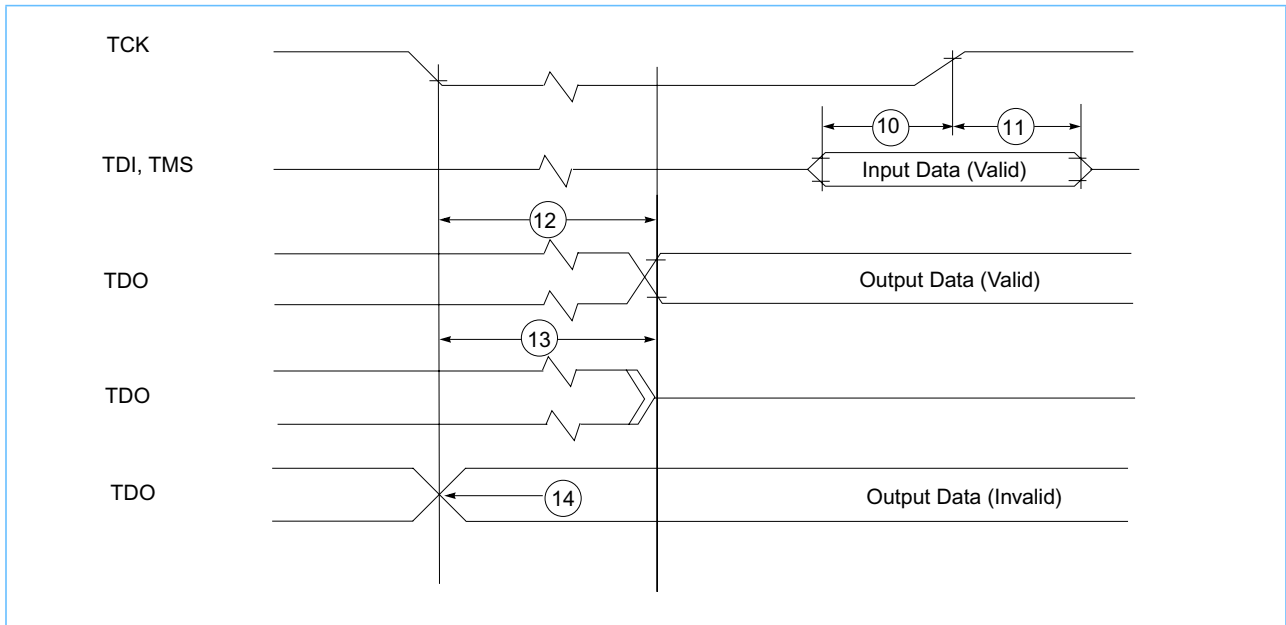


Figure 3-10. Test Access Port Timing Diagram



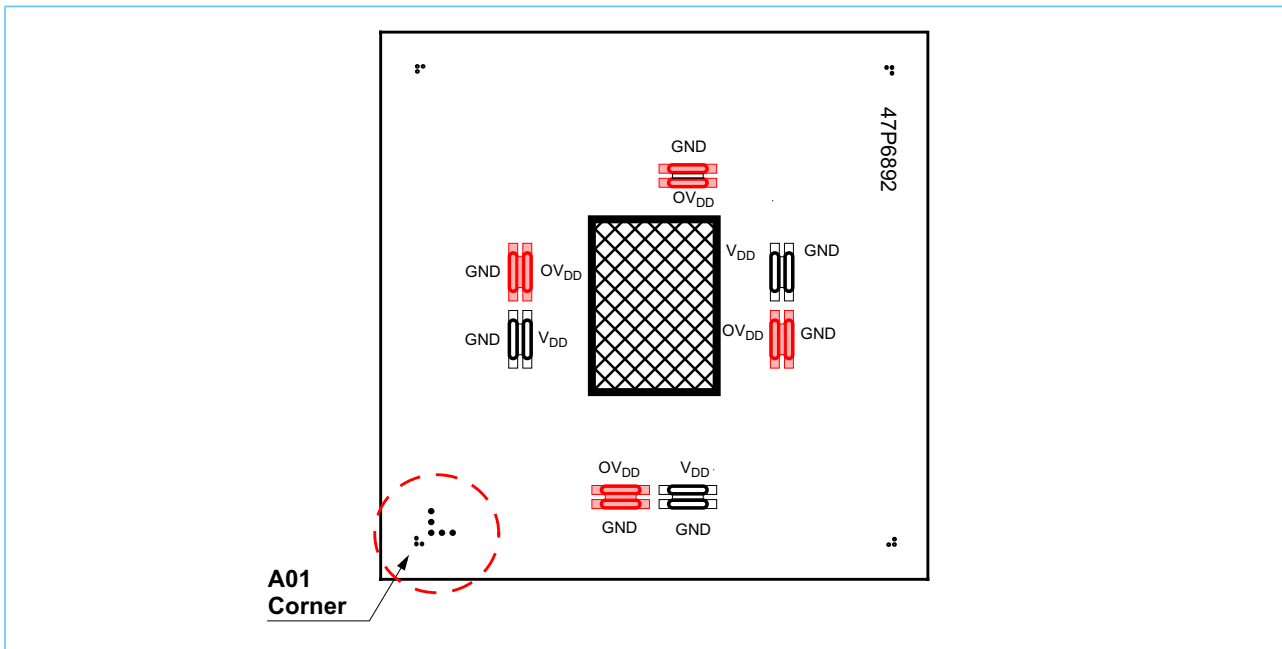
## 4. Dimensions and Signal Assignments

IBM offers a ceramic ball grid array (CBGA) which supports 292 balls for the 750FX package.

### 4.1 Module Substrate Decoupling Voltage Assignments

The on-board substrate voltage-to-ground assignments for the capacitor locations are shown in *Figure 4-1*.

*Figure 4-1. Module Substrate Decoupling Voltage Assignments*



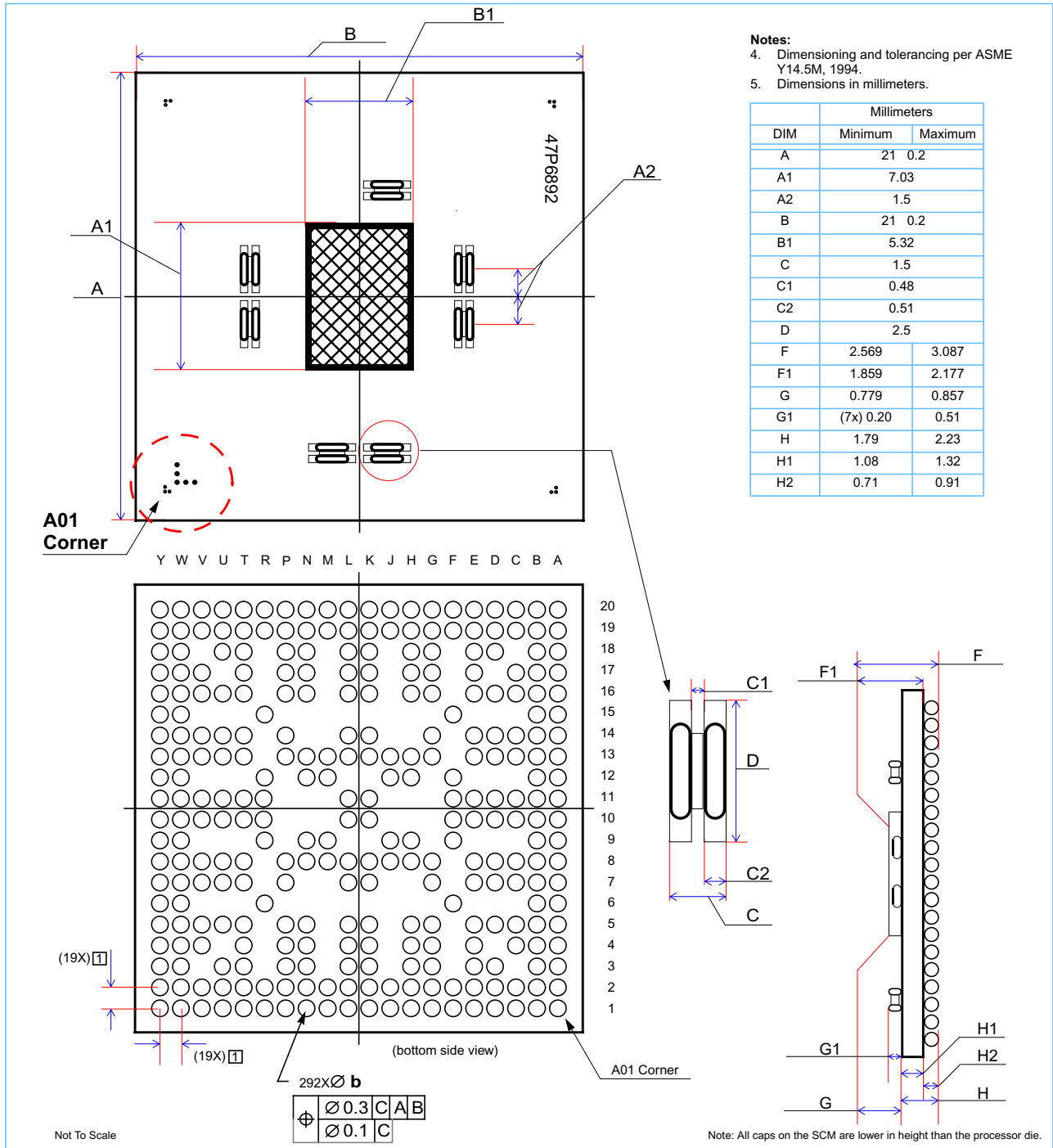
### 4.2 Package

Module mass is approximately 3.25 grams. Ball pitch is 1 mm. Ball diameter target is 0.8 mm +/- 0.04 mm. JEDEC moisture sensitivity level is 1. For pad, line, via, and dogbone recommendations, ask for "Printed Wiring Board Tech For 1.0 mm Pitch Modules."

**Note:** Use A01 corner designation for correct placement. Use the five plated dots that form a right angle (└) to locate the A01 corner as shown in *Figure 4-2 Mechanical Dimensions and Bottom Surface Nomenclature of the CBGA Package* on page 23.



Figure 4-2. Mechanical Dimensions and Bottom Surface Nomenclature of the CBGA Package



### 4.3 Microprocessor Ball Placement

Figure 4-3. PowerPC 750FX Microprocessor Ball Placement

20	A6	A8	A3	A2	A0	DH31	DH25	DH26	DP2	DH22	DH19	DH18	DH16	DH15	DH14	DP0	DH9	DH10	DH4	DH2	
19	A13	GND	A5	A4	A1	DH29	DP3	DH28	DH23	DH24	DH21	DH20	DP1	DH17	DH11	DH8	DH6	DH5	GND	DH3	
18	A11	A10		OVDD	GND		OVDD	GND		VDD	VDD		GND	OVDD		GND	OVDD		DH0	PLL_CFG0	
17	A12	TT1	OVDD		A9		DH30	DH27		GND	GND		DH12	DH13		DH1		OVDD	PLL_CFG1	PLL_CFG2	
16	A14	A15	GND	AP0	A7		GND	OVDD		OVDD	OVDD		OVDD	GND		DH7	PLL_CFG3	GND	SYSCLK	A2VDD	
15	TT3	TS					VDD									VDD				PLL_RNG0	A1VDD
14	TSIZ0	TT2	OVDD	TT0	GND		OVDD			GND	GND			OVDD		GND	PLL_RNG1	OVDD	PLL_CFG4	AGND	
13	AP2	TT4	GND	AP1	VDD		GND	GND	VDD	VDD	VDD	VDD	GND	GND		VDD	LLSD_MODE	GND	L2_TSTCLK	L1_TSTCLK	
12	TA	TSIZ1					VDD		GND	GND			GND	GND		VDD				MCP	CHECKSTOP
11	TBST	TSIZ2	VDD	GND	OVDD	GND				VDD	VDD					GND	OVDD	GND	VDD	TLBISYNC	HRESET
10	DBDIS	A16	VDD	GND	OVDD	GND				GND	GND					GND	OVDD	GND	VDD	SMI	CKSTP
9	A18	A17					VDD		GND	VDD			VDD	GND		VDD				BVSEL	INT
8	AACK	AP3	GND	A21	VDD		GND	GND	VDD	VDD	VDD	VDD	GND	GND		VDD	QREQ	GND	TBEN	QACK	
7	A20	A19	OVDD	A24	GND		OVDD			GND	GND			OVDD		GND	DBB	OVDD	ARTRY	SRESET	
6	DBWO	A23					VDD									VDD				TEA	ABB
5	A22	A26	GND	A25	A31		GND	OVDD		OVDD	OVDD		OVDD	GND		CLK_OUT	WT	GND	TDO	DBG	
4	A28	A27	OVDD		DL3		DP5	DL13		GND	GND		DL23	DL26		CI		OVDD	BG	RSRV	
3	A29	A30		OVDD	GND		OVDD	GND		VDD	VDD		GND	OVDD		GND	OVDD		DRTRY	BR	
2	DL0	GND	DL2	DL6	DL5	DL11	DL10	DL12	DL16	DL15	DL19	DL20	DL22	DL27	DL28	TCK	DL30	TDI	GND	BLANK	
1	DL1	DP4	DL4	DL8	DL7	DL9	DL14	DP6	DL18	DL17	DL21	DP7	DL24	DL25	DL29	DL31	TRST	TMS	GBL	BLANK	
	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	T	U	V	W	Y	

**Note:** This view is looking down from above the 750FX placed and soldered on the system board.

## 4.4 Pinout Listings

Table 4-1 contains the pinout listing for the 750FX CBGA package.

Table 4-1. Pinout Listing for the CBGA package

Signal Name	Pin Number	Active	Input/Output	Notes
A[0:31]	E20, E19, D20, C20, D19, C19, A20, E16, B20, E17, B18, A18, A17, A19, A16, B16, B10, B9, A9, B7, A7, D8, A5, B6, D7, D5, B5, B4, A4, A3, B3, E5.	High	Input/Output	
A1VDD	Y15	—	—	
A2VDD	Y16	—	—	
AACK	A8	Low	Input	
ABB	Y6	Low	Input/Output	
AGND	Y14	—	—	
AP[0:3]	D16, D13, A13, B8	High	Input/Output	6
ARTRY	W7	Low	Input/Output	
BG	W4	Low	Input	
BLANK	Y1, Y2	—	—	3
BR	Y3	Low	Output	
BVSEL	W9	—	Input	4
CHECKSTOP (CKSTP_OUT)	Y12	Low	Output	
CI	T4	Low	Output	
CKSTP_IN	Y10	Low	Input	
CLK_OUT	T5	High	Output	
DBB	U7	Low	Input/Output	
DBDIS	A10	Low	Input	
DBG	Y5	Low	Input	
DBW0	A6	Low	Input	
DH[0:31]	W18, T17, Y20, Y19, W20, V19, U19, T16, T19, U20, V20, R19, N17, P17, R20, P20, N20, P19, M20, L20, M19, L19, K20, J19, K19, G20, H20, H17, H19, F19, G17, F20	High	Input/Output	
DL[0:31]	A2, A1, C2, E4, C1, E2, D2, E1, D1, F1, G2, F2, H2, H4, G1, K2, J2, K1, J1, L2, M2, L1, N2, N4, N1, P1, P4, P2, R2, R1, U2, T1	High	Input/Output	
DP[0:7]	T20, N19, J20, G19, B1, G4, H1, M1	High	Input/Output	6
DRTRY	W3	Low	Input	
GBL	W1	Low	Input/Output	

### Notes:

1. These are test signals for factory use only and must be pulled up to  $OV_{DD}$  for normal machine operation.
2.  $OV_{DD}$  inputs supply power to the Input/Output drivers and  $V_{DD}$  inputs supply power to the processor core.
3. These pins are reserved for potential future use.
4. BVSEL and L1\_TSTCLK select the Input/Output voltage mode on the 60x bus (see Section 5.7 on page 49).
5. TCK must be tied high or low for normal machine operation.
6. Address and data parity should be left floating if unused in the design.

Table 4-1. Pinout Listing for the CBGA package (Continued)

Signal Name	Pin Number	Active	Input/Output	Notes
GND	B2, B19, C5, C8, C13, C16, D10, D11, E3, E7, E14, E18, F10, F11, G5, G8, G13, G16, H3, H8, H9, H12, H13, H18, J12, K4, K7, K10, K14, K17, L4, L7, L10, L14, L17, M12, N3, N8, N9, N12, N13, N18, P5, P8, P13, P16, R10, R11, T3, T7, T14, T18, U10, U11, V5, V8, V13, V16, W2, W19,	—	—	
HRESET	Y11	Low	Input	
INT	Y9	Low	Input	
L1_TSTCLK	Y13	High	Input	4
L2_TSTCLK	W13	High See note 1.	Input	1
LSSD_MODE	U13	Low	Input	1
MCP	W12	Low	Input	
OV <sub>DD</sub>	C4, C7, C14, C17, D3, D18, E10, E11, G3, G7, G14, G18, H5, H16, K5, K16, L5, L16, N5, N16, P3, P7, P14, P18, T10, T11, U3, U18, V4, V7, V14, V17	—	—	2
PLL_CFG[0:4]	Y18, W17, Y17, U16, W14	High	Input	
PLL_RNG[0:1]	W15, U14	High	Input	
QACK	Y8	Low	Input	
QREQ	U8	Low	Output	
RSRV	Y4	Low	Output	
SMI	W10	Low	Input	
SRESET	Y7	Low	Input	
SYSCLK	W16	High	Input	
TA	A12	Low	Input	
TBEN	W8	High	Input	
TBST	A11	Low	Input/Output	
TCK	T2	High	Input	5
TDI	V2	High	Input	
TDO	W5	High	Output	
TEA	W6	Low	Input	
TLBISYNC	W11	Low	Input	
TMS	V1	High	Input	
TRST	U1	Low	Input	
TS	B15	Low	Input/Output	

**Notes:**

1. These are test signals for factory use only and must be pulled up to OV<sub>DD</sub> for normal machine operation.
2. OV<sub>DD</sub> inputs supply power to the Input/Output drivers and V<sub>DD</sub> inputs supply power to the processor core.
3. These pins are reserved for potential future use.
4. BVSEL and L1\_TSTCLK select the Input/Output voltage mode on the 60x bus (see *Section 5.7* on page 49).
5. TCK must be tied high or low for normal machine operation.
6. Address and data parity should be left floating if unused in the design.



Table 4-1. Pinout Listing for the CBGA package (Continued)

Signal Name	Pin Number	Active	Input/Output	Notes
TSIZ[0:2]	A14, B12, B11	High	Output	
TT[0:4]	D14, B17, B14, A15, B13	High	Input/Output	
$V_{DD}$	C10, C11, E8, E13, F6, F9, F12, F15, J8, J9, J13, K3, K8, K11, K13, K18, L3, L8, L11, L13, L18, M8, M9, M13, R6, R9, R12, R15, T8, T13, V10, V11	—	—	2
$\overline{WT}$	U5	Low	Output	

**Notes:**

1. These are test signals for factory use only and must be pulled up to  $OV_{DD}$  for normal machine operation.
2.  $OV_{DD}$  inputs supply power to the Input/Output drivers and  $V_{DD}$  inputs supply power to the processor core.
3. These pins are reserved for potential future use.
4. BVSEL and L1\_TSTCLK select the Input/Output voltage mode on the 60x bus (see *Section 5.7* on page 49).
5. TCK must be tied high or low for normal machine operation.
6. Address and data parity should be left floating if unused in the design.

Table 4-2. Signal Locations

Signal	Ball Location	Signal	Ball Location	Signal	Ball Location	Signal	Ball Location
A0	E20	DH0	W18	DL0	A2	AACK	A8
A1	E19	DH1	T17	DL1	A1	ABB	Y6
A2	D20	DH2	Y20	DL2	C2	AGND	Y14
A3	C20	DH3	Y19	DL3	E4	ARTRY	W7
A4	D19	DH4	W20	DL4	C1	BG	W4
A5	C19	DH5	V19	DL5	E2	BR	Y3
A6	A20	DH6	U19	DL6	D2	BVSEL	W9
A7	E16	DH7	T16	DL7	E1	CHECKSTOP (CKSTP_OUT)	Y12
A8	B20	DH8	T19	DL8	D1	CI	T4
A9	E17	DH9	U20	DL9	F1	CLK_OUT	T5
A10	B18	DH10	V20	DL10	G2	CKSTP (CKSTP_IN)	Y10
A11	A18	DH11	R19	DL11	F2	DBB	U7
A12	A17	DH12	N17	DL12	H2	DBDIS	A10
A13	A19	DH13	P17	DL13	H4	DBG	Y5
A14	A16	DH14	R20	DL14	G1	DBWO	A6
A15	B16	DH15	P20	DL15	K2	DRTRY	W3
A16	B10	DH16	N20	DL16	J2	GBL	W1
A17	B9	DH17	P19	DL17	K1	HRESET	Y11
A18	A9	DH18	M20	DL18	J1	INT	Y9
A19	B7	DH19	L20	DL19	L2	L1_TSTCLK	Y13
A20	A7	DH20	M19	DL20	M2	L2_TSTCLK	W13
A21	D8	DH21	L19	DL21	L1	LSSD_MODE	U13
A22	A5	DH22	K20	DL22	N2	MCP	W12
A23	B6	DH23	J19	DL23	N4	PLL_CFG0	Y18
A24	D7	DH24	K19	DL24	N1	PLL_CFG1	W17
A25	D5	DH25	G20	DL25	P1	PLL_CFG2	Y17
A26	B5	DH26	H20	DL26	P4	PLL_CFG3	U16
A27	B4	DH27	H17	DL27	P2	PLL_CFG4	W14
A28	A4	DH28	H19	DL28	R2	PLL_RNG0	W15
A29	A3	DH29	F19	DL29	R1	PLL_RNG1	U14
A30	B3	DH30	G17	DL30	U2	QACK	Y8
A31	E5	DH31	F20	DL31	T1	QREQ	U8
						RSRV	Y4
						SMI	W10
						SRESET	Y7
						SYSCLK	W16



Table 4-2. Signal Locations (Continued)

Signal	Ball Location	Signal	Ball Location	Signal	Ball Location	Signal	Ball Location
		AP0	D16	DP0	T20	$\overline{TA}$	A12
		AP1	D13	DP1	N19	TBEN	W8
		AP2	A13	DP2	J20	$\overline{TBST}$	A11
		AP3	B8	DP3	G19	TCK	T2
				DP4	B1	TDI	V2
				DP5	G4	TDO	W5
				DP6	H1	$\overline{TEA}$	W6
				DP7	M1	$\overline{TLBISYNC}$	W11
						TMS	V1
						$\overline{TRST}$	U1
						$\overline{TS}$	B15
						TSIZ0	A14
						TSIZ1	B12
						TSIZ2	B11
						TT0	D14
						TT1	B17
						TT2	B14
						TT3	A15
						TT4	B13
						$\overline{WT}$	U5

Table 4-3. Voltage and Ground Assignments

A1V <sub>DD</sub>	A2V <sub>DD</sub>	OV <sub>DD</sub>	OV <sub>DD</sub>	V <sub>DD</sub>	V <sub>DD</sub>	GND	GND
Y15	Y16	C4	C7	C10	C11	B2	B19
		C14	C17	E8	E13	C5	C8
		D3	D18	F6	F9	C13	C16
		E10	E11	F12	F15	D10	D11
		G3	G7	J8	J9	E3	E7
		G14	G18	J13	K3	E14	E18
		H5	H16	K8	K11	F10	F11
		K5	K16	K13	K18	G5	G8
		L5	L16	L3	L8	G13	G16
		N5	N16	L11	L13	H3	H8
		P3	P7	L18	M8	H9	H12
		P14	P18	M9	M13	H13	H18
		T10	T11	R6	R9	J12	K4
		U3	U18	R12	R15	K7	K10
		V4	V7	T8	T13	K14	K17
		V14	V17	V10	V11	L4	L7
						L10	L14
						L17	M12
						N3	N8
						N9	N12
						N13	N18
						P5	P8
						P13	P16
						R10	R11
						T3	T7
						T14	T18
						U10	U11
						V5	V8
						V13	V16
						W2	W19



## 5. System Design Information

This section provides electrical and thermal design recommendations for successful application of the 750FX. For more information, see the PowerPC FAQ, the PowerPC 750FX Errata list, any applicable PCNs, and the other PowerPC documentation and application notes in the PowerPC Technical Library on our web site.

### 5.1 PLL Considerations

The 750FX design includes two PLLs (PLL0 and PLL1), allowing the processor clock frequency to dynamically change between the PLL frequencies via software control. Use the bits in the HID1 register to specify:

1. The frequency range of each PLL
2. The clock multiplier for each PLL
3. External or internal control of PLL0
4. The selected PLL (which is the source of the processor clock at any given time)

For HID1 bit definitions, see the *PowerPC 750 FX User's Manual*.

**Note:** The PLL configuration must adhere to the supported frequency range as specified in this document and in the *IBM 750FX Datasheet Supplement for DD2.X Product Revisions*, for the minimum  $V_{DD}$  condition. Voltages ( $V_{DD}/AV_{DD}$ ) should remain constant at all times.

At power-on reset, the HID1 register contains zeroes for all the non-read-only bits (bits 7 to 31). This configuration corresponds to the selection of PLL0 as the source of the processor clocks and selects the external configuration and range pins to control PLL0. The external configuration and range pin values are accessible to software using HID1 read-only bits 0-6. PLL1 is always controlled by its internal configuration and range bits. The HID1 setting associated with hard reset corresponds to a PLL1 configuration of clock off, and selection of the medium frequency range.

$\overline{HRESET}$  must be asserted during power up long enough for the PLL(s) to lock, and for the internal hardware to be reset. Once this timing is satisfied,  $\overline{HRESET}$  can be negated. The processor now will proceed to execute instructions, clocked by PLL0 as configured via the external pins. The processor clock frequency can be modified from this initial setting in one of two ways. First, as with earlier designs,  $\overline{HRESET}$  can be asserted, and the external configuration pins can be set to a new value. The machine state is lost in this process, and, as always,  $\overline{HRESET}$  must be held asserted while the PLL relocks, and the internal state is reset. Second, the introduction of another PLL provides an alternative means of changing the processor clock frequency, which does not involve the loss of machine state nor a delay for PLL relock.

The following sequence can be used to change processor clock frequency.

**Note:** Assume PLL0 is currently the source for the processor clock.

1. Configure PLL1 to produce the desired clock frequency by setting HID1[PR1] and HID1[PC1] to the appropriate values.
2. Wait for PLL1 to lock. The lock time is the same for both PLLs and is provided in the hardware specification.
3. Set HID1[PS] to 1 to initiate the transition from PLL0 to PLL1 as the source of the processor clocks. From the time the HID1 register is updated to select the new PLL, the transition to the new clock frequency will complete within three (3) bus cycles. After the transition, the HID(PSS) bit indicates which PLL is in use.

After both PLLs are running and locked, the processor frequency can be toggled with very low latency. For example, when it is time to change back to the PLL0 frequency, there is no need to wait for PLL lock. HID1[PS] can be reset to 0, causing the processor clock source to transition from PLL1 back to PLL0. If PLL0 will not be needed for some time, it can be configured to be off while not in use. This is done by resetting the HID1[PC0] field to 0, and setting HID1[PI0] to 1. Turning the non-selected PLL off results in a modest power savings, but introduces added latency when changing frequency. If PLL0 is configured to be off, the procedure for switching to PLL0 as the selected PLL involves changing the configuration and range bits, waiting for lock, and then selecting PLL0, as described in the previous paragraph.

### 5.1.1 Restrictions and Considerations for PLL Configuration

#### Avoid the following when reconfiguring the PLLs:

1. The configuration and range bits in HID1 should only be modified for the non-selected PLL, since it will require time to lock before it can be used as the source for the processor clock.
2. The HID1[PI0] bit should only be modified when PLL0 is not selected.
3. Whenever one of the PLLs is reconfigured, it must not be selected as the active PLL until enough time has elapsed for the PLL to lock.
4. At all times, the frequency of the processor clock, as determined by the various configuration settings, must be within the specification range for the current operating conditions.
5. Never select a PLL that is in the 'off' configuration.

#### 5.1.1.1 Configuration Restriction on Frequency Transitions

It is considered a programming error to switch from one PLL to the other when both are configured in a *half-cycle* multiplier mode. For example, with PLL0 configured in 9:2 mode (cfg = 01001) and PLL1 configured in 13:2 mode (cfg = 01101), changing the select bit (HID1[PS]) is not allowed. In cases where such a pairing of configurations is desired, an intermediate full-cycle configuration must be used between the two half-cycle modes. For example, with PLL0 at 9:2, PLL1, configured at 6:1 is selected, then PLL0 is reconfigured at 13:2, locked and selected.

### 5.1.2 PLL\_RNG[0:1] Definitions for Dual PLL Operation

The dual PLLs on the 750FX are configured by the PLL\_CFG[0:4] and PLL\_RNG[0:1] signals. For a given SYCLK (bus) frequency, the PLL configuration signals set the internal CPU and VCO frequency of operation. The PLL range configuration, for dual PLL operation, for the 750FX is shown in the following table.

Table 5-1. PLL\_RNG [0:1] Definitions for Dual PLL Operation

PLL_RNG[0:1]	PLL Frequency Range
00	600 MHz and above
10	Below 600 MHz
01	Reserved
11	Reserved

### 5.1.3 PLL Configuration

PLL-CFG (*Table 5-2*) must be set so that both SYSCLK and the core frequency are within the Clock AC Timing Specifications shown in *Table 3-6* on page 13. In addition, the core frequency must not exceed the limit specified in the part number, and the system must meet the required specifications.

*Table 5-2. 750FX Microprocessor PLL Configuration*

PLL_CFG [0:4]		Processor to Bus Frequency Ratio (PBFR)
Binary	Decimal	
00000	0	OFF
00001	1	OFF
00010	2	PLL Bypass <sup>2</sup>
00011	3	PLL Bypass <sup>2</sup>
00100	4	2x <sup>1</sup>
00101	5	2.5x <sup>1</sup>
00110	6	3x
00111	7	3.5x
01000	8	4x
01001	9	4.5x
01010	10	5x
01011	11	5.5x
01100	12	6x
01101	13	6.5x
01110	14	7x
01111	15	7.5x
10000	16	8x
10001	17	8.5x
10010	18	9x
10011	19	9.5x
10100	20	10x
10101	21	11x
10110	22	12x
10111	23	13x
11000	24	14x
11001	25	15x
11010	26	16x

**Notes:**

1. The 2X- 2.5X Processor to Bus Ratios are currently not supported.
2. In PLL-bypass mode, the SYSCLK input signal clocks the internal processor directly, the PLL is disabled, and the bus mode is set for 1:1 mode operation. This mode is intended for factory use only.  
The AC timing specifications given in the document do not apply in PLL-bypass mode.
3. In Clock-off mode, no clocking occurs inside the 750FX regardless of the SYSCLK input.

Table 5-2. 750FX Microprocessor PLL Configuration (Continued)

PLL_CFG [0:4]		Processor to Bus Frequency Ratio (PBFR)
Binary	Decimal	
11011	27	17x
11100	28	18x
11101	29	19x
11110	30	20x
11111	31	Off <sup>3</sup>

**Notes:**

1. The 2X- 2.5X Processor to Bus Ratios are currently not supported.
2. In PLL-bypass mode, the SYSCLK input signal clocks the internal processor directly, the PLL is disabled, and the bus mode is set for 1:1 mode operation. This mode is intended for factory use only.  
The AC timing specifications given in the document do not apply in PLL-bypass mode.
3. In Clock-off mode, no clocking occurs inside the 750FX regardless of the SYSCLK input.

## 5.2 PLL Power Supply Filtering

The 750FX microprocessor has two separate  $AV_{DD}$  signals ( $A1V_{DD}$  and  $A2V_{DD}$ ) which provide power to the clock generation phase-locked loops.

Most designs are expected to utilize a single PLL configuration mode throughout the application. These type of designs should use the default,  $A1V_{DD}$  (PLL0) and tie the  $A2V_{DD}$  (PLL1) signal to ground (AGND) through a 100 ohm resistor. This is shown in *Figure 5-1* on page 36.

For designs planning to optimize power savings through dynamic switching between these dual PLL circuits, it is recommended, though not required, that each  $AV_{DD}$  have a separate voltage input and filter circuit.

To ensure stability of the internal clock, the power supplied to the  $AV_{DD}$  input signals should be filtered using a circuit similar to the one shown in *Figure 5-1* on page 36. The circuit should be placed as close as possible to the  $AV_{DD}$  pin to ensure it filters out as much noise as possible.

For descriptions of the sample PLL power supply filtering circuits, see *Table 5-3*.

*Table 5-3. Sample PLL Power Supply Filtering Circuits*

Samples of PLL Power Supply Filtering Circuits					
Circuit Description	Number of Filtering Circuits	Ferrite Beads	Circuit Figure	Recommended Circuit Design	Notes
Single PLL circuit configuration that uses the $A1V_{DD}$ and ties the $A2V_{DD}$ pin to GND.	1	1	<i>Figure 5-1</i> on page 36	Yes	
Single PLL circuit configuration that uses both the $A1V_{DD}$ and the $A2V_{DD}$ pins and a single ferrite bead.	1	1	<i>Figure 5-2</i> on page 37	Optional	1, 2
Dual PLL configuration that uses a separate circuit for the $A1V_{DD}$ pin and for the $A2V_{DD}$ the pin.	2	2	<i>Figure 5-3</i> on page 38	Yes	2, 3

**Notes:**

- Optional configurations are supported, though not recommended.
- This circuit design can be used with the Dual PLL feature enabled, though optimum power savings may not be realized. For additional information, see *Figure 5-3 Dual PLL Power Supply Filter Circuits* on page 38.
- This circuit design can be used with the Dual PLL feature enabled to optimize power savings.

Figure 5-1. Single PLL Power Supply Filter Circuit with A1V<sub>DD</sub> Pin and A2V<sub>DD</sub><sup>2</sup> Pin Tied to GND

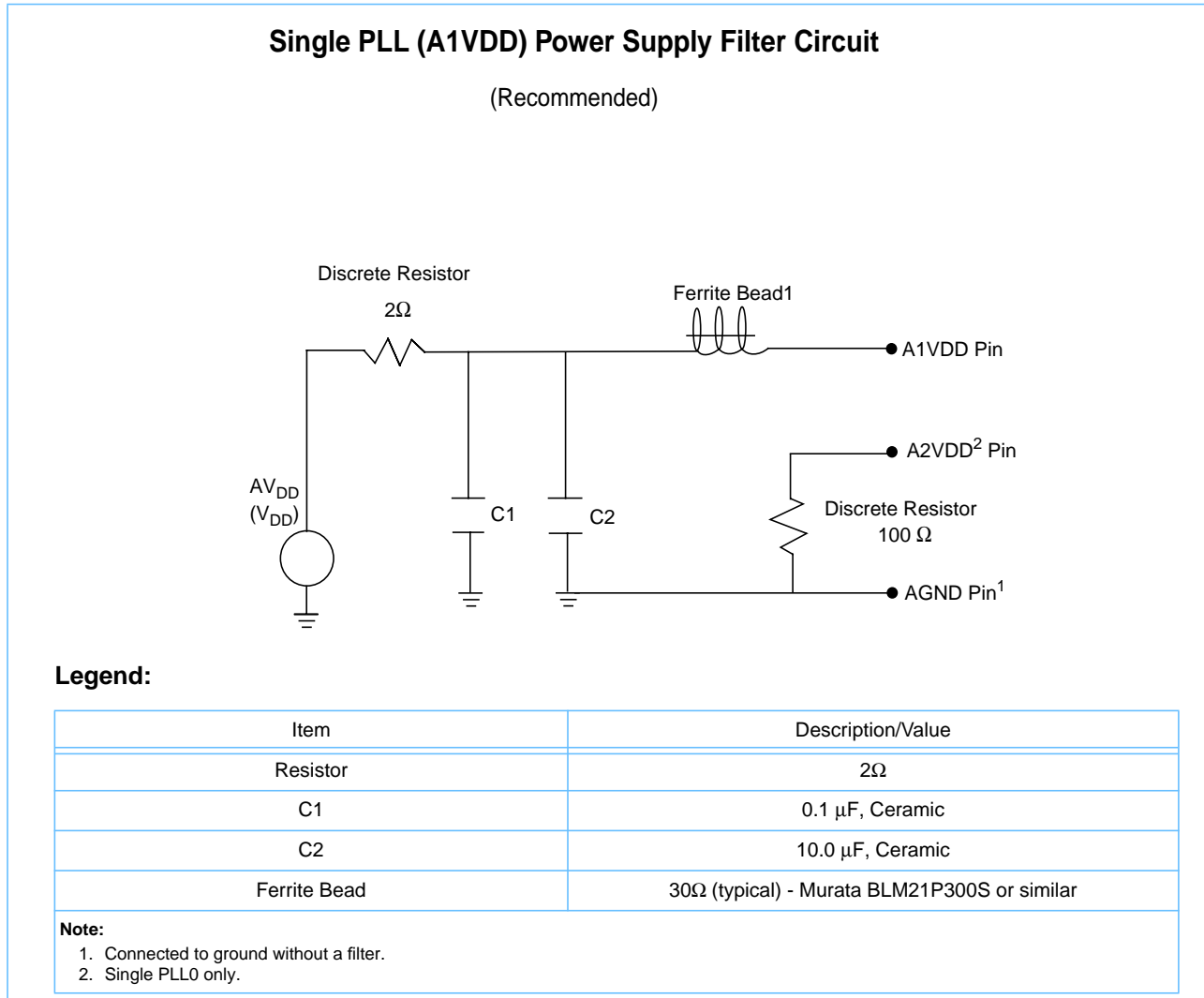


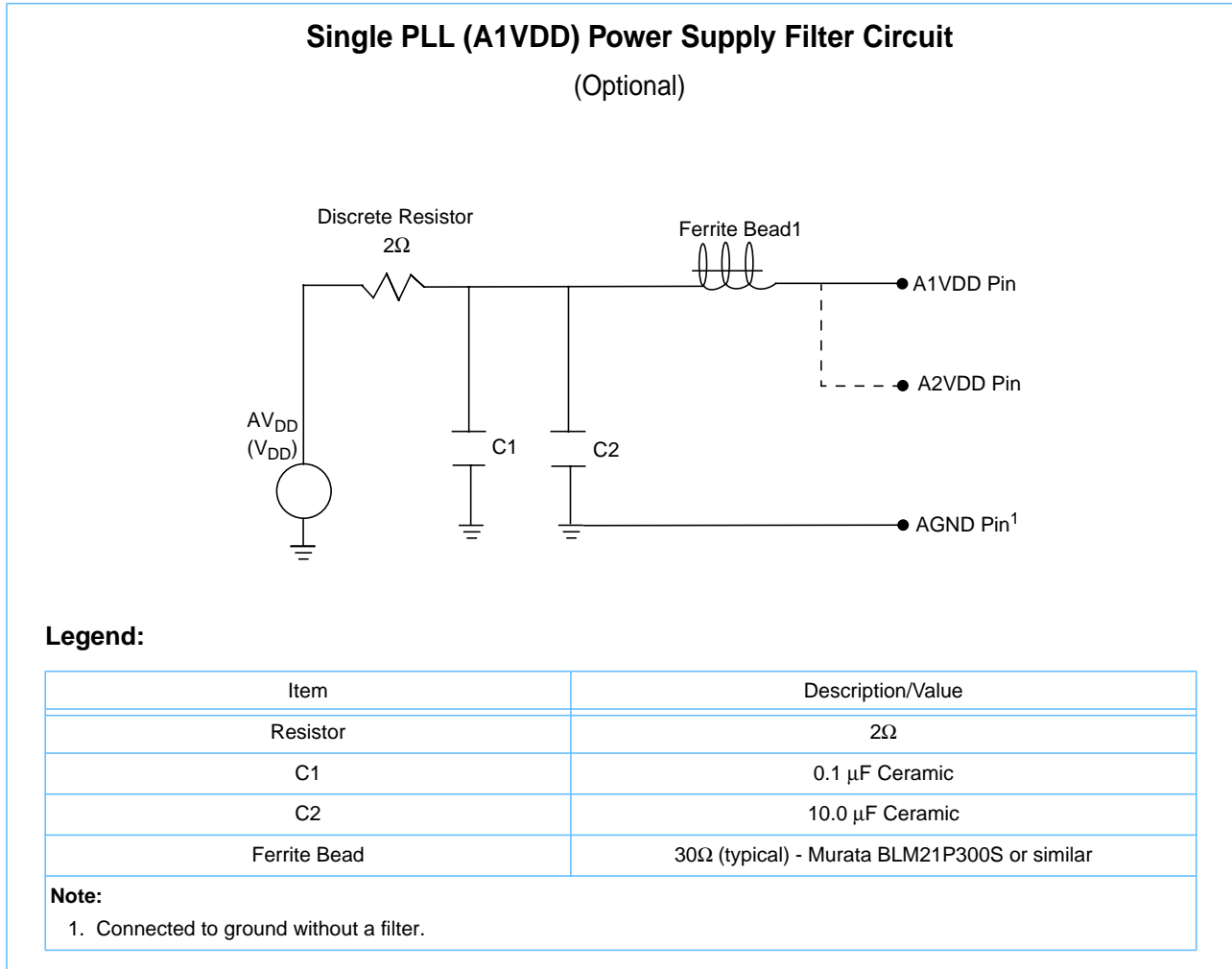
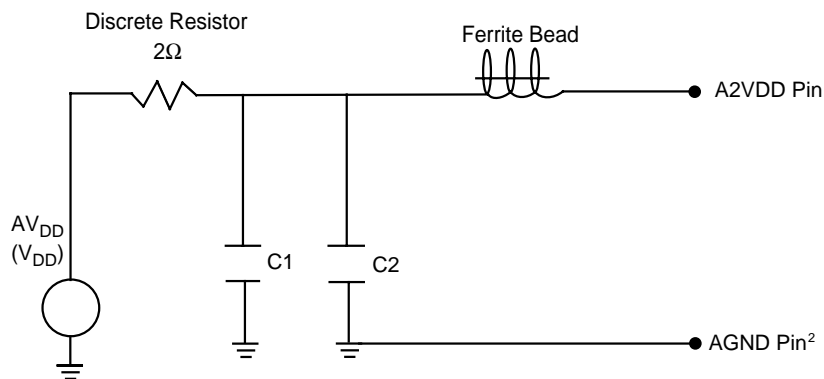
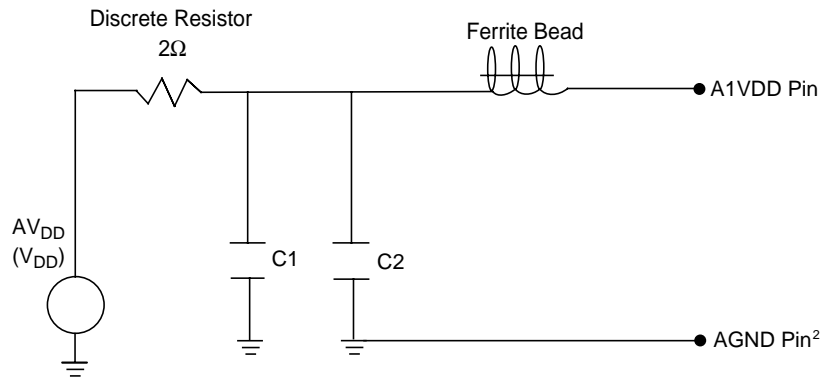
Figure 5-2. PLL Power Supply Filter Circuit with Two AV<sub>DD</sub> Pins and One Ferrite


Figure 5-3. Dual PLL Power Supply Filter Circuits

### Dual PLL (AVDD) Power Supply Filter Circuits<sup>1</sup>

(Recommended configuration if Dual PLL feature is enabled.)



Item	Description/Value
Resistor	2Ω
C1	0.1 μF Ceramic
C2	10.0 μF Ceramic
Ferrite Bead	30Ω (typical) - Murata BLM21P300S or similar

**Notes:**

1. The dual PLL power supply circuits shown in this figure are recommended for a design that uses the Dual PLL feature. For more information about the Dual PLL feature, see *Section 5.2 Low Voltage Operation at Lower Frequency* on page 40.
2. Connected to ground without a filter.



### 5.3 Decoupling Recommendations

Capacitor decoupling is required for the 750FX. Decoupling capacitors act to reduce high frequency chip switching noise and provide localized bulk charge storage to reduce major power surge effects.

High frequency decoupling capacitors should be located as close as possible to the processor with low lead inductance to the ground and voltage planes.

Decoupling capacitors are recommended on the back of the card, directly opposite the module. The recommended placement and number of decoupling capacitors, 34  $V_{DD}$ -GND caps and 44  $OV_{DD}$ -GND caps are described in *Figure 5-4 Orientation and Layout of the 750FX Decoupling Capacitors*. The recommended decoupling capacitor specifications are provided in *Table 5-4 Recommended Decoupling Capacitor Specifications*. The placement and usage described here are guidelines for decoupling capacitors and should be applied for system designs.

*Table 5-4. Recommended Decoupling Capacitor Specifications*

Item	Description
Decoupling capacitor specifications:	Type X5R or Y5V 10V minimum 0402 size 40 x 20 mils, nominally 1.0 mm x 0.5 mm 0.1 mm on both dimensions 100 nF
Recommended minimum number of decoupling capacitors on the back of the card:	34 $V_{DD}$ -GND caps 44 $OV_{DD}$ -GND caps

The decoupling capacitor electrodes are located directly opposite from their corresponding BGA pins where possible. Also, each electrode for each decoupling capacitor needs to be connected to one or more BGA pins (balls) with a short electrical path. Thus, through-vias adjacent to the decoupling capacitors are recommended.

The card designer can expand on the decoupling capacitor recommendations by doing the following:

- Adding additional decoupling capacitors  
If using additional decoupling capacitors, verify that these additional capacitors do not reduce the number of card vias or cause the vias to lose proximity to each capacitor electrode.
- Adding additional through-vias or blind-vias  
Card technologies are available that will reduce the inductance between the decoupling capacitor and the BGA pin (ball). Replacing single vias with multiple vias is very effective. Place GND vias close to  $V_{DD}$  or  $OV_{DD}$  vias to reduce loop inductance.

For more information on power layout and bypassing, see the IBM Application Note, "PowerPC 750FX Layout and Bypassing."

Figure 5-4. 750FX Pin Locations:  $OV_{DD}$ ,  $V_{DD}$ , GND, and Signal Pins

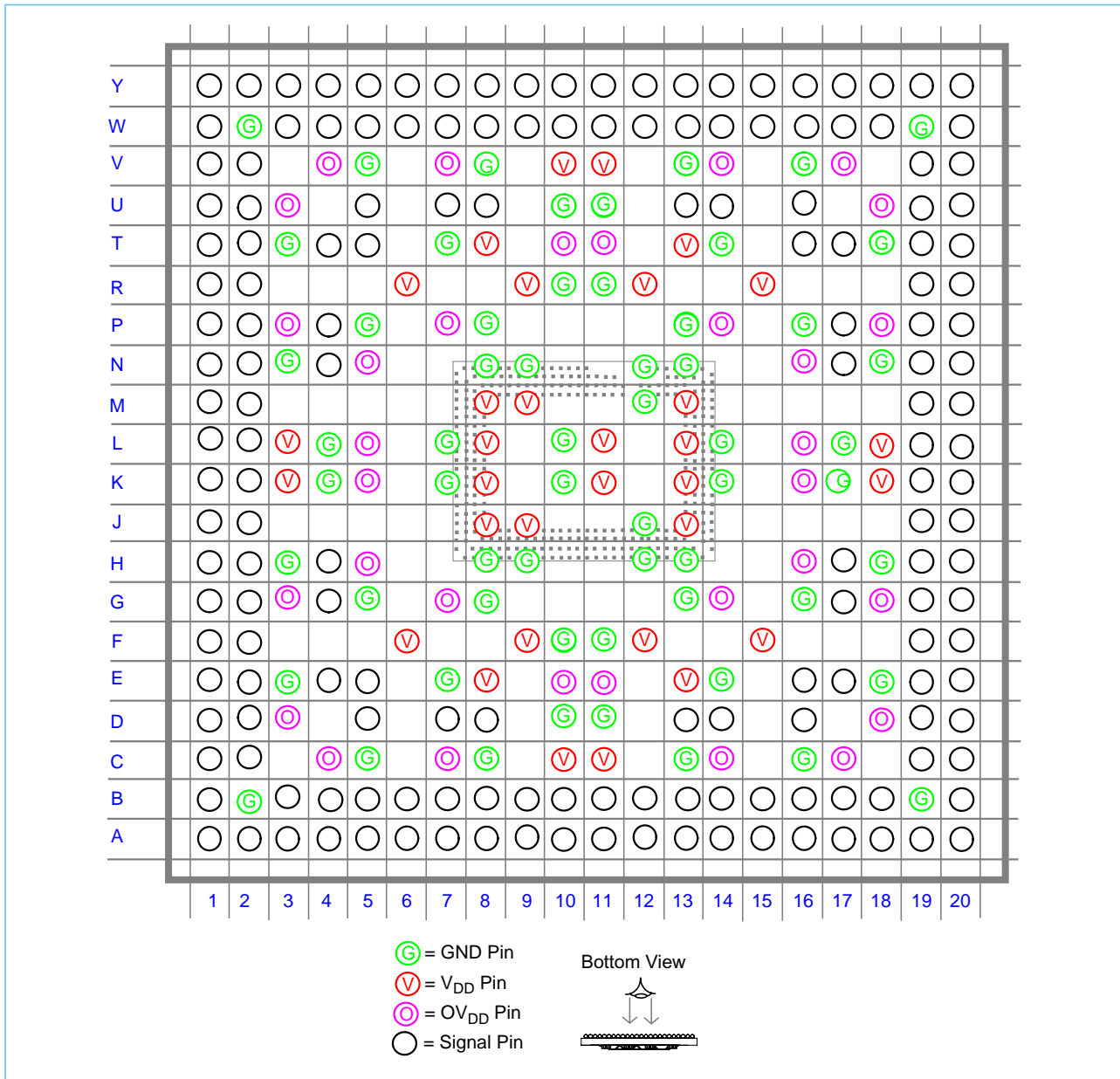
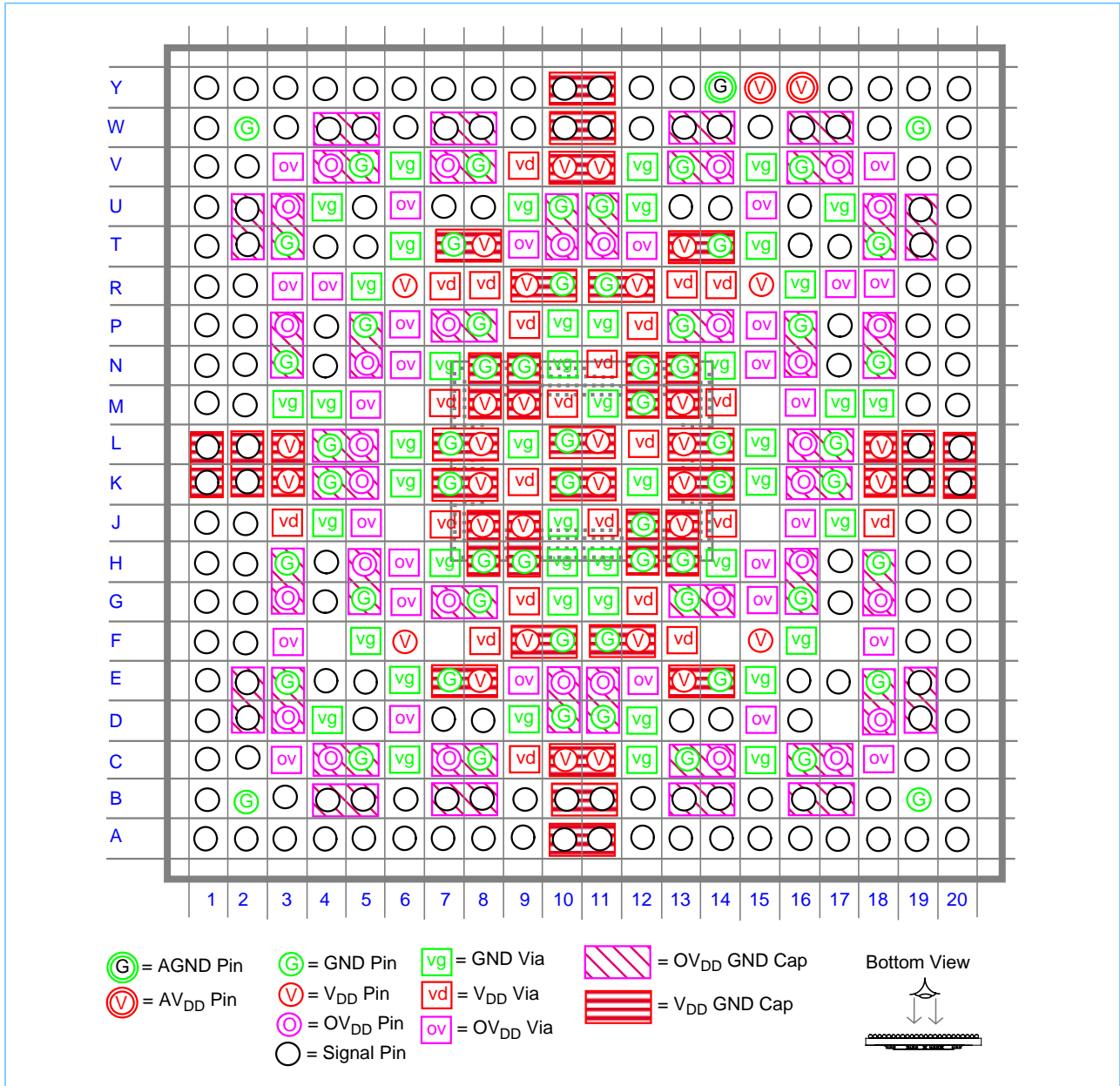


Figure 5-5. Orientation and Layout of the 750FX Decoupling Capacitors



## 5.4 Output Buffer DC Impedance

The 750FX 60x drivers were characterized over various process, voltage, and temperature conditions. To measure  $Z_0$ , an external resistor is connected to the chip pad, either to  $OV_{DD}$  or GND. Then the value of such resistor is varied until the pad voltage is  $OV_{DD}/2$  (see Figure 5-6).

The output impedance is actually the average of two resistances: the resistance of the pull-up and the resistance of pull-down devices. When Data is held low, SW1 is closed (SW2 is open), and  $R_N$  is trimmed until  $Pad = OV_{DD}/2$ .  $R_N$  then becomes the resistance of the pull-down devices. When Data is held high, SW2 is closed (SW1 is open), and  $R_P$  is trimmed until  $Pad = OV_{DD}/2$ .  $R_P$  then becomes the resistance of the pull-up devices. With a properly designed driver  $R_P$  and  $R_N$  are close to each other in value, then  $Z_0 = (R_P + R_N)/2$ .

Figure 5-6. Driver Impedance Measurement

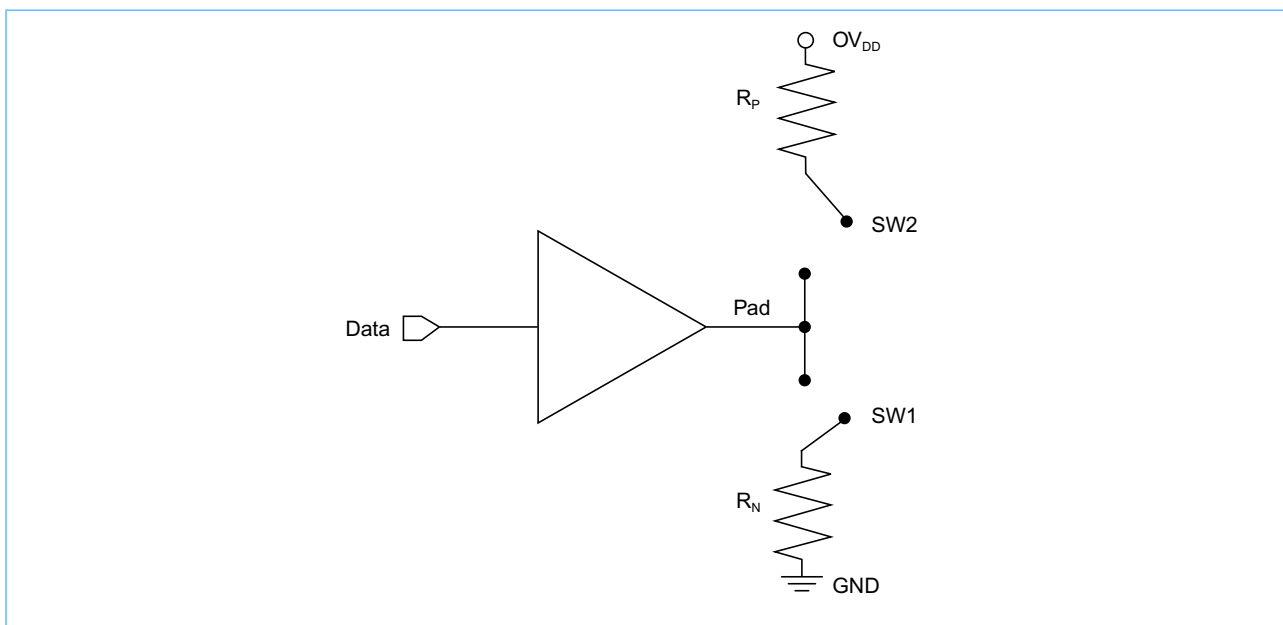


Table 5-5 summarizes the driver impedance characteristics a designer uses to design a typical process.

Table 5-5. Driver Impedance Characteristics

Process	60x Impedance ( $\Omega$ )	OV <sub>DD</sub> (V)	Temperature ( $^{\circ}$ C)
Worst	50	1.70	105
Typical	44	1.80	65
Best	36	1.90	0
Worst	50	2.38	105
Typical	44	2.50	65
Best	36	2.63	0
Worst	65	3.14	105
Typical	50	3.30	65
Best	35	3.46	0

### 5.4.1 Input-Output Usage

Table 5-6 *Input-Output Usage* provides details on the input-output usage of the PowerPC 750FX RISC Microprocessor signals. The *Usage Group* column refers to the general functional category of the signal.

In the PowerPC 750FX RISC Microprocessor, certain input-output signals have pullups and pulldowns, which may or may not be enabled. In Table 5-6, the *Input/Output with Internal Resistors* column defines which signals have these pullups or pulldowns and their active or inactive state. The *Level Protect* column defines which signals have the designated function added to their Input/Output cell. For more about Level Protection, see Section 5.5 *Level Protection* on page 48.

**Caution:** This section is based on preliminary information and is subject to change.

Pull L2\_TSTCLK and  $\overline{\text{LSSD\_MODE}}$  high for normal operation.

Pins shown as No Connect (NC) must not be connected.

Connect all GND pins to ground. Connect all V<sub>DD</sub> and OV<sub>DD</sub> pins to the appropriate supply.



Table 5-6. Input-Output Usage

750FX Signal Name	Active Level	Input/Output	Usage Group	Input/Output with Internal Pullup Resistors	Level Protect	Required External Resistor	Comments	Notes
A1V <sub>DD</sub>	—	—	Power Supply					
A2V <sub>DD</sub>	—	—	Power Supply					
A[0:31]	High	Input/Output	Address Bus		Keeper			1, 3, 4
AACK	Low	Input	Address Termination		Keeper		Must be actively driven	3, 4, 5
ABB	Low	Input/Output			Keeper	5K Ω	Pullup required to OV <sub>DD</sub>	3, 4, 5
AGND	—	—	Power Supply					
AP[0:3]	High	Input/Output			Keeper			3, 4
ARTRY	Low	Input/Output	Address Termination		Keeper	5K Ω	Pullup required to OV <sub>DD</sub>	3, 4, 5
BG	Low	Input	Address Arbitration		Keeper		Active driver or pulldown	3, 4, 5
BR	Low	Output	Address Arbitration		Keeper		Chip actively drives	3, 4, 5
BVSEL	N/A	Input	Input/Output Level			5K Ω	Pullup/pulldown, as required	5
CHECKSTOP	Low	Output	Interrupt/Resets		Keeper	5K Ω	Pullup required to OV <sub>DD</sub>	3, 4, 5
CI	Low	Output	Transfer Attributes		Keeper			1, 3, 4
CKSTP_IN	Low	Input	Interrupt/Resets		Keeper		Must be actively driven	3, 4, 5
CLK_OUT	High	Output			Keeper			3, 4
DBB	Low	Input/Output			Keeper	5K Ω	Pullup required to OV <sub>DD</sub>	3, 4, 5
DBDIS	Low	Input			Keeper			3, 4
DBG	Low	Input	Data Arbitration		Keeper		Active driver or tie low	3, 4, 5
DBWO	Low	Input			Keeper			3, 4

**Notes:**

1. Depends on the system design. The electrical characteristics of the 750FX do not add additional constraints to the system design, so whatever is done with the net will depend on the system requirements.
2. HRESET, SRESET, and TRST are signals used for ESP and RISCWatch to enable proper operation of the debuggers. Logical AND gates should be placed between these signals and PowerPC 750FX RISC Microprocessor. (Refer to Figure 5-7 on page 48.)
3. The 750FX provides protection from meta-stability on inputs through the use of a “keeper” circuit on specific inputs. Refer to *Level Protection on page 48* for a more detailed description.
4. If a system design requires a signal level to be maintained while not being actively driven, an external resistor or device must be used (Keepers assure no meta-stability of inputs but do not guarantee a level).
5. The 750FX does not require external pullups on address and data lines. Control lines must be treated individually.

Table 5-6. Input-Output Usage (Continued)

750FX Signal Name	Active Level	Input/Output	Usage Group	Input/Output with Internal Pullup Resistors	Level Protect	Required External Resistor	Comments	Notes
DH[0:31]	High	Input/Output	Data Bus		Keeper			1, 3, 4
DL[0:31]	High	Input/Output	Data Bus		Keeper			1, 3, 4
DP[0:7]	High	Input/Output						
$\overline{\text{DRTRY}}$	Low	Input			Keeper			3, 4
$\overline{\text{GBL}}$	Low	Input/Output	Transfer Attributes		Keeper			1, 3, 4
GND	—	—	Power Supply					
$\overline{\text{HRESET}}$	Low	Input	Interrupt/Resets		Keeper		Active driver	2, 3, 4, 5
$\overline{\text{INT}}$	Low	Input	Interrupt/Resets		Keeper		Active driver or pullup	3, 4, 5
L1_TSTCLK	High	Input	LSSD	Not enabled		5K $\Omega$	Pullup/pulldown, as required	5
L2_TSTCLK	High	Input	LSSD	Not enabled		5K $\Omega$	Pullup required to $\text{OV}_{\text{DD}}$	5
$\overline{\text{LSSD\_MODE}}$	Low	Input	LSSD	Not enabled		5K $\Omega$	Pullup required to $\text{OV}_{\text{DD}}$	5
$\overline{\text{MCP}}$	Low	Input	Interrupt/Resets		Keeper		Active driver or pullup	3, 4, 5
$\text{OV}_{\text{DD}}$	—	—	Power Supply					
PLL_CFG[0:4]	High	Input	Clock Control		Keeper	As required	Pullup/pulldown, as required	3, 4, 5
PLL_RNG[0:1]	High	Input			Keeper	As required	Pullup/pulldown, as required	3, 4, 5
$\overline{\text{QACK}}$	Low	Input	Control		Keeper		Must be actively driven	3, 4, 5
$\overline{\text{QREQ}}$	Low	Output	Status/Control		Keeper		Chip actively drives	3, 4, 5
$\overline{\text{RSRV}}$	Low	Output			Keeper		No connect	3, 4, 5
$\overline{\text{SMI}}$	Low	Input			Keeper			3, 4
$\overline{\text{SRESET}}$	Low	Input	Interrupt/Resets		Keeper		Active driver or pullup	2, 3, 4, 5

**Notes:**

1. Depends on the system design. The electrical characteristics of the 750FX do not add additional constraints to the system design, so whatever is done with the net will depend on the system requirements.
2.  $\overline{\text{HRESET}}$ ,  $\overline{\text{SRESET}}$ , and  $\overline{\text{TRST}}$  are signals used for ESP and RISCWatch to enable proper operation of the debuggers. Logical AND gates should be placed between these signals and PowerPC 750FX RISC Microprocessor. (Refer to Figure 5-7 on page 48.)
3. The 750FX provides protection from meta-stability on inputs through the use of a "keeper" circuit on specific inputs. Refer to *Level Protection on page 48* for a more detailed description.
4. If a system design requires a signal level to be maintained while not being actively driven, an external resistor or device must be used (Keepers assure no meta-stability of inputs but do not guarantee a level).
5. The 750FX does not require external pullups on address and data lines. Control lines must be treated individually.





Table 5-6. Input-Output Usage (Continued)

750FX Signal Name	Active Level	Input/Output	Usage Group	Input/Output with Internal Pullup Resistors	Level Protect	Required External Resistor	Comments	Notes
SYCLK	High	Input	Clock Control		Keeper	No resistor by design	Active driver	3, 4, 5
$\overline{TA}$	Low	Input	Data Termination		Keeper		Active driver	3, 4, 5
TBEN	High	Input						
$\overline{TBST}$	Low	Input/Output	Transfer Attributes		Keeper			1, 3, 4
TCK	High	Input	JTAG	Not enabled		External pulldown	5K $\Omega$ to GND	5
TDI	High	Input	JTAG	Enabled high	Internal enabled		50 $\mu$ a@2.5V 25 $\mu$ a@1.8V (the pullup current for the internal resistor)	5
TDO	High	Output	JTAG		Keeper			3, 4
$\overline{TEA}$	Low	Input	Data Termination		Keeper		Active driver or pullup	3, 4, 5
$\overline{TLBISYNC}$	Low	Input	Control		Keeper		Must be actively driven	3, 4
TMS	High	Input	JTAG	Enabled high	Internal enabled		50 $\mu$ a@2.5V 25 $\mu$ a@1.8V (the pullup current for the internal resistor)	5
$\overline{TRST}$	Low	Input	JTAG	Enabled high	Internal enabled		50 $\mu$ a@2.5V 25 $\mu$ a@1.8V (the pullup current for the internal resistor)	2, 5
$\overline{TS}$	Low	Input/Output	Address Start		Keeper	5K $\Omega$	Pullup required to OV <sub>DD</sub>	3, 4, 5
TSIZ[0:2]	High	Output	Transfer Attributes		Keeper			1, 3, 4

**Notes:**

1. Depends on the system design. The electrical characteristics of the 750FX do not add additional constraints to the system design, so whatever is done with the net will depend on the system requirements.
2.  $\overline{HRESET}$ ,  $\overline{SRESET}$ , and  $\overline{TRST}$  are signals used for ESP and RISCWatch to enable proper operation of the debuggers. Logical AND gates should be placed between these signals and PowerPC 750FX RISC Microprocessor. (Refer to Figure 5-7 on page 48.)
3. The 750FX provides protection from meta-stability on inputs through the use of a "keeper" circuit on specific inputs. Refer to *Level Protection on page 48* for a more detailed description.
4. If a system design requires a signal level to be maintained while not being actively driven, an external resistor or device must be used (Keepers assure no meta-stability of inputs but do not guarantee a level).
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Preliminary

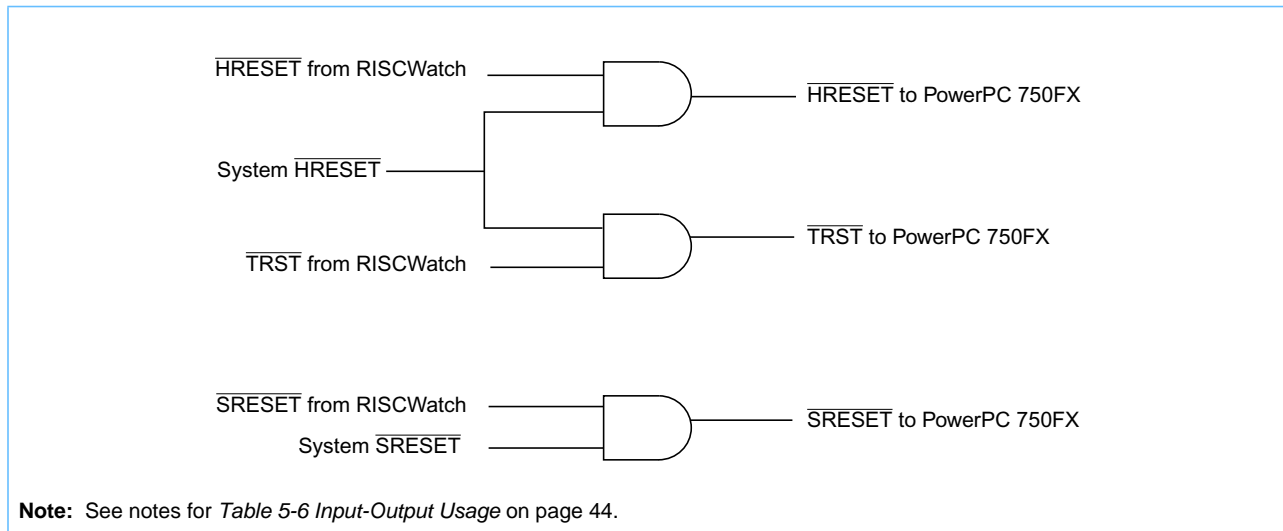
Table 5-6. Input-Output Usage (Continued)

750FX Signal Name	Active Level	Input/Output	Usage Group	Input/Output with Internal Pullup Resistors	Level Protect	Required External Resistor	Comments	Notes
TT[0:4]	High	Input/Output	Transfer Attributes		Keeper			1, 3, 4
V <sub>DD</sub>	—	—	Power Supply					
WT	Low	Output	Transfer Attributes		Keeper			1, 3, 4

**Notes:**

1. Depends on the system design. The electrical characteristics of the 750FX do not add additional constraints to the system design, so whatever is done with the net will depend on the system requirements.
2.  $\overline{\text{HRESET}}$ ,  $\overline{\text{SRESET}}$ , and  $\overline{\text{TRST}}$  are signals used for ESP and RISCWatch to enable proper operation of the debuggers. Logical AND gates should be placed between these signals and PowerPC 750FX RISC Microprocessor. (Refer to Figure 5-7 on page 48.)
3. The 750FX provides protection from meta-stability on inputs through the use of a “keeper” circuit on specific inputs. Refer to *Level Protection on page 48* for a more detailed description.
4. If a system design requires a signal level to be maintained while not being actively driven, an external resistor or device must be used (Keepers assure no meta-stability of inputs but do not guarantee a level).
5. The 750FX does not require external pullups on address and data lines. Control lines must be treated individually.

Figure 5-7. IBM RISCWatch™ JTAG to  $\overline{HRESET}$ ,  $\overline{TRST}$ , and  $\overline{SRESET}$  Signal Connector



## 5.5 Level Protection

A level protection feature is included in the PowerPC 750FX RISC Microprocessor. The level protection feature is available in the 1.8V, 2.5V, and 3.3V bus modes. This feature prevents ambiguous floating reference voltages by pulling the respective signal line to the last valid or nearest valid state.

For example, if the Input/Output voltage level is closer to  $OV_{DD}$ , the circuit pulls the I/O level to  $OV_{DD}$ . If the I/O level is closer to GND, the I/O level is pulled low. This self-latching circuitry *keeps* the floating inputs defined and avoids meta-stability. In *Table 5-6 Input-Output Usage* on page 44, these signals are defined as *keeper* in the *Level Protect* column.

Keepers are not intended to force a net to a particular state. The keeper supplies a small (100  $\mu A$  max.) amount of current, which is intended to help keep a net at the current logic state.

The level protect circuitry provides no additional leakage current to the signal I/O; however, some amount of current must be applied to the *keeper* node to overcome the level protection latch. This current is process dependent, but in no case is the current required over 100 $\mu A$ .

This feature allows the system designer to limit the number of resistors in the design and optimize placement and reduce costs.

**Note:** Having a level protection (keeper) on the associated signal I/O does not replace a pull-up or pull-down resistor that is needed by the 750FX or a separate device located on the 60x bus. The designer must supply any such resistors.

## 5.6 64 or 32-Bit Data Bus Mode

This mode selection varies for different design revision (DD) levels. For the 750FX DD2.X, mode setting is determined by the state of the mode signal,  $\overline{\text{TLBISYNC}}$ , at the transition of  $\overline{\text{HRESET}}$  from low to high. If  $\overline{\text{TLBISYNC}}$  is **high** when  $\overline{\text{HRESET}}$  transitions from active to inactive, 64-bit mode is selected. If  $\overline{\text{TLBISYNC}}$  is **low** when  $\overline{\text{HRESET}}$  transitions from active to inactive, 32-bit mode is selected.

**Special Note:** (Reduced pin out mode) To transition from a previous processor with reduced pin out mode, drive  $\overline{\text{TLBISYNC}}$  appropriately, leave the DP(0..7) and AP(0..3) pins floating, and disable parity checking. The 750FX does not have APE and DPE pins.

## 5.7 I/O Voltage Mode Selection

Selection between 1.8V, 2.5V, or 3.3V I/O modes is accomplished by using the BVSEL and L1\_TSTCLK pins:

- If BVSEL = 1 and L1\_TSTCLK = 0, then the 3.3V mode is enabled.
- If BVSEL = 1 and L1\_TSTCLK = 1, then the 2.5V mode is enabled.
- If BVSEL = 0 and L1\_TSTCLK = 1, then the 1.8V mode is enabled.

**Note:** Do not set BVSEL = 0 and L1\_TSTCLK = 0 since it yields an INVALID MODE.

Table 5-7. Summary of Mode Select

Mode	750FX (DD2.x)
32-bit mode	Sample $\overline{\text{TLBISYNC}}$ to select HIGH = 64-bit mode LOW = 32-bit mode
I/O mode selection	3.3V +/- 165mV (BVSEL = 1, L1_TSTCLK = 0) or 2.5V +/- 125mV (BVSEL = 1, L1_TSTCLK = 1) or 1.8V +/- 100mV (BVSEL = 0, L1_TSTCLK = 1)

## 5.8 Thermal Management

This section provides thermal management information for the CBGA package for air cooled applications. Proper thermal control design is primarily dependent upon the system-level design; that is, the heat sink, air flow, and the thermal interface material. To reduce the die-junction temperature, heat sinks may be attached to the package by several methods: adhesive, spring clip to holes in the printed-circuit board or package, mounting clip, or a screw assembly, see *Figure 5-10 Package Exploded Cross-Sectional View with Several Heat Sink Options* on page 54.

In general, a heat sink is required for all 750FX applications.

A design example is included in this section.

### 5.8.1 Heat Sink Selection Example

For preliminary heat sink sizing, the die-junction temperature can be expressed as follows:

$$T_J = T_A + T_R + (\theta_{JC} + \theta_{INT} + \theta_{SA}) \times P_D$$

**Where:**

$T_J$  is the die-junction temperature

$T_A$  is the inlet cabinet ambient temperature

$T_R$  is the air temperature rise within the system cabinet

$\theta_{JC}$  is the junction-to-case thermal resistance

$\theta_{INT}$  is the thermal resistance of the thermal interface material

$\theta_{SA}$  is the heat sink-to-ambient thermal resistance

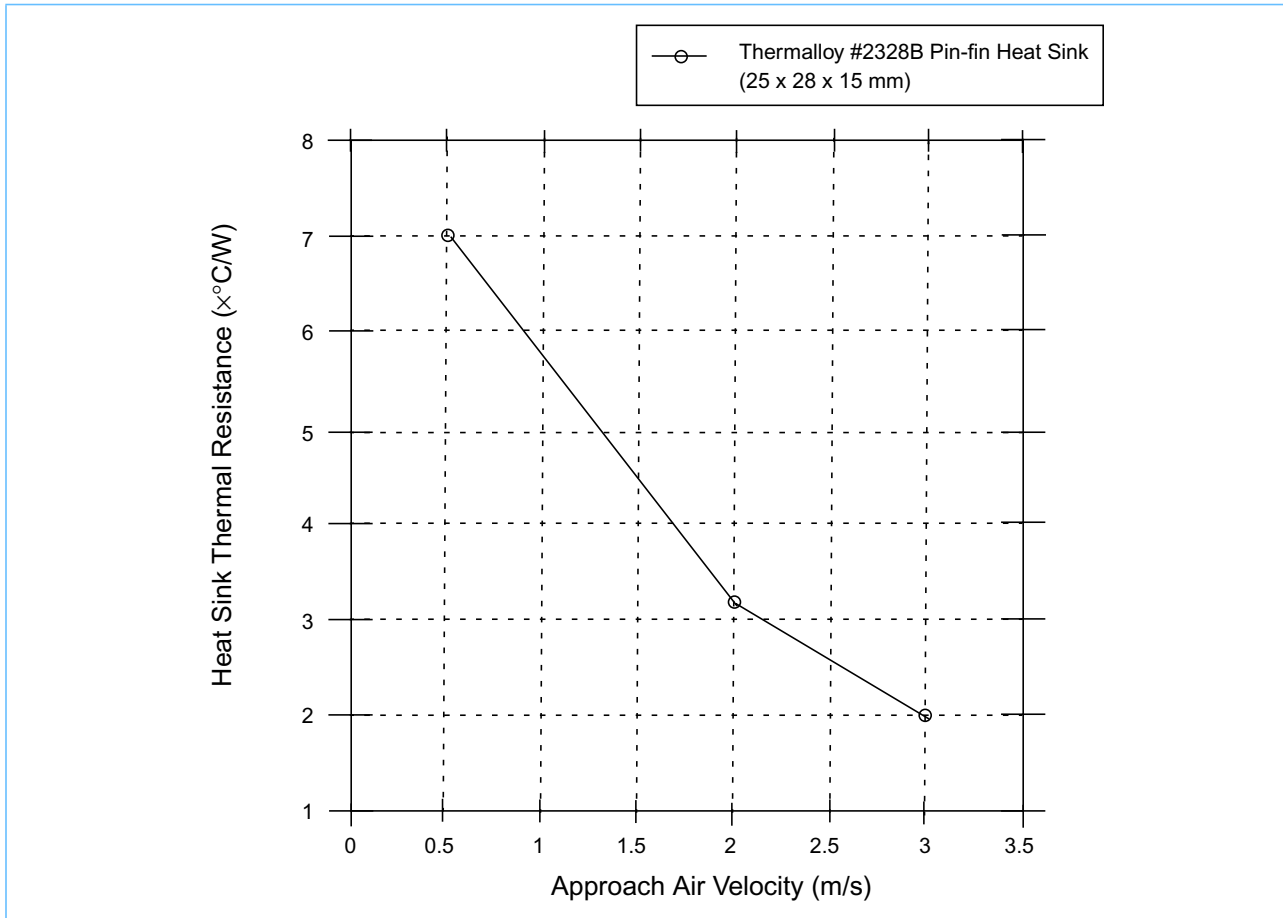
$P_D$  is the power dissipated by the device

Typical die-junction temperatures ( $T_J$ ) should be maintained less than the value specified in *Table 3-3 Package Thermal Characteristics 1* on page 10. The temperature of the air cooling the component greatly depends upon the ambient inlet air temperature and the air temperature rise within the computer cabinet. An electronic cabinet inlet-air temperature ( $T_A$ ) may range from 30 to 40°C. The air temperature rise within a cabinet ( $T_R$ ) may be in the range of 5 to 10°C. The thermal resistance of the interface material ( $\theta_{INT}$ ) is typically about 1°C/W. Assuming a  $T_A$  of 30°C, a  $T_R$  of 5°C, a CBGA package  $\theta_{JC} = 0.03$ , and a power dissipation ( $P_D$ ) of 5.0 watts, the following expression for  $T_J$  is obtained.

$$\text{Die-junction temperature: } T_J = 30^\circ\text{C} + 5^\circ\text{C} + (0.03^\circ\text{C/W} + 1.0^\circ\text{C/W} + \theta_{SA}) \times 5\text{W}$$

For a Thermalloy heat sink #2328B, the heat sink-to-ambient thermal resistance ( $\theta_{SA}$ ) versus air flow velocity is shown in *Figure 5-8 Thermalloy #2328B Pin-Fin Heat Sink-to-Ambient Thermal Resistance vs. Airflow Velocity* on page 51.

Figure 5-8. Thermalloy #2328B Pin-Fin Heat Sink-to-Ambient Thermal Resistance vs. Airflow Velocity



Assuming an air velocity of 0.5m/s, we have an effective  $\theta_{SA}$  of 7°C/W, thus

$$T_j = 30^\circ\text{C} + 5^\circ\text{C} + (2.2^\circ\text{C/W} + 1.0^\circ\text{C/W} + 7^\circ\text{C/W}) \times 4.5\text{W},$$

resulting in a junction temperature of approximately 81°C which is well within the maximum operating temperature of the component.

Other heat sinks offered by Chip Coolers, IERC, Thermalloy, Aavid, and Wakefield Engineering offer different heat sink-to-ambient thermal resistances, and may or may not need air flow.

Though the junction-to-ambient and the heat sink-to-ambient thermal resistances are a common figure-of-merit used for comparing the thermal performance of various microelectronic packaging technologies, one should exercise caution when only using this metric in determining thermal management because no single parameter can adequately describe three-dimensional heat flow. The final chip-junction operating temperature is not only a function of the component-level thermal resistance, but the system-level design and its operating conditions. In addition to the component's power dissipation, a number of factors affect the final operating die-junction temperature. These factors might include air flow, board population (local heat flux of adjacent components), heat sink efficiency, heat sink attach, next-level interconnect technology, system air temperature rise, and so forth.

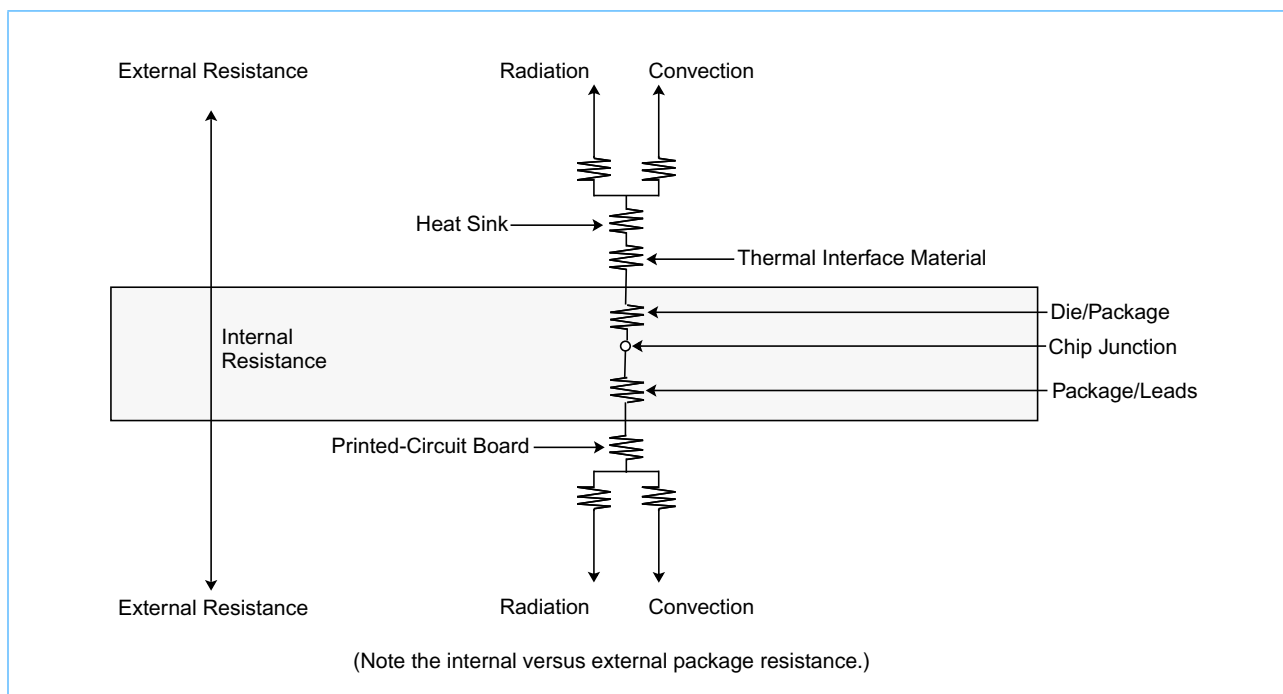
### 5.8.2 Internal Package Conduction

For the exposed-die packaging technology, shown in *Table 3-3 Package Thermal Characteristics 1* on page 10, the intrinsic conduction thermal resistance paths are as follows.

- Die junction-to-case thermal resistance (Primary thermal path)
- Die junction-to-lead thermal resistance (Not normally a significant thermal path)
- Die junction-to-ambient thermal resistance (Largely dependent on customer-supplied heatsink)

Figure 5-9 depicts the primary heat transfer path for a package with an attached heat sink mounted to a printed-circuit board.

Figure 5-9. C4 Package with Heat Sink Mounted to a Printed-Circuit Board



Heat generated on the active side (ball) of the chip is conducted through the silicon, then through the heat sink attach material (or thermal interface material), and finally to the heat sink; where it is removed by forced-air convection. Since the silicon thermal resistance is quite small, for a first-order analysis, the temperature drop in the silicon may be neglected. Thus, the heat sink attach material and the heat sink conduction/convective thermal resistances are the dominant terms.

The heat flow path from the die, through the chip-to-substrate balls, through the substrate, through the substrate-to-board balls, and through the board to ambient is usually too high of a resistance to offer much cooling. In addition, various factors make the heat flow through this path very difficult to accurately determine. Designers must not depend on cooling the 750FX using this means unless thermal modeling has been confidently completed.

### 5.8.3 Minimum Heat Sink Requirements

The worst-case power dissipation (PD) for the 750FX is shown in Table 3-5. A conservative thermal management design will provide sufficient cooling to maintain the junction temperature ( $T_J$ ) of the 750FX below 105C at maximum PD and worst-case ambient temperature and airflow conditions.

Many factors affect the 750FX power dissipation, including  $V_{DD}$ ,  $T_J$ , core frequency, process factors, and the code that is running on the processor. In general, PD increases with increases in  $T_J$ ,  $V_{DD}$ ,  $F_{core}$ , process variables, and the number of instructions executed per second.

For various reasons, a designer may determine that the power dissipation of the 750FX in their application will be less than the maximum value shown in the Datasheet. Assuming a lower PD will result in a thermal management system with less cooling capacity than would be required for the maximum Datasheet PD. In this case, the designer may decide to determine the actual maximum 750FX PD in the particular application. Contact your IBM PowerPC FAE for more information.

In addition to the system factors that must be considered in a cooling system analysis, three things should be noted. First, 750FX PD rises as  $T_J$  increases, so it is most useful to measure PD while the 750FX junction temperature is at maximum. While not specified or guaranteed, this rise in PD with  $T_J$  is typically less than 1W per 10C. So regardless of other factors, the minimum cooling solution must have a maximum temperature rise of no more than 10C/W.

This minimum cooling solution is not generally achievable without a heat sink. A heat sink or heat spreader of some sort must always be used in 750FX applications.

Second, due to process variations, there can be a significant variation in the PD of individual 750FX devices. In addition, IBM will occasionally supply "downbinned" parts. These are faster parts that are shipped in lieu of the speed that was ordered. For example, some parts that are marked as 600MHz may actually run as fast as 700MHz. These 700MHz parts will dissipate more power at 600MHz than the 600MHz parts. So power dissipation analysis should be conducted using the fastest parts available.

Finally, regardless of methodology, IBM only supports system designs that successfully maintain the maximum junction temperature within Datasheet limits. IBM also supports designs that rely on the maximum PD values given in this Datasheet, and supply a cooling solution sufficient to dissipate that amount of power while keeping the maximum junction temperature below the maximum  $T_J$ .

### 5.8.4 Heat Sink Mounting

Figure 5-10. Package Exploded Cross-Sectional View with Several Heat Sink Options

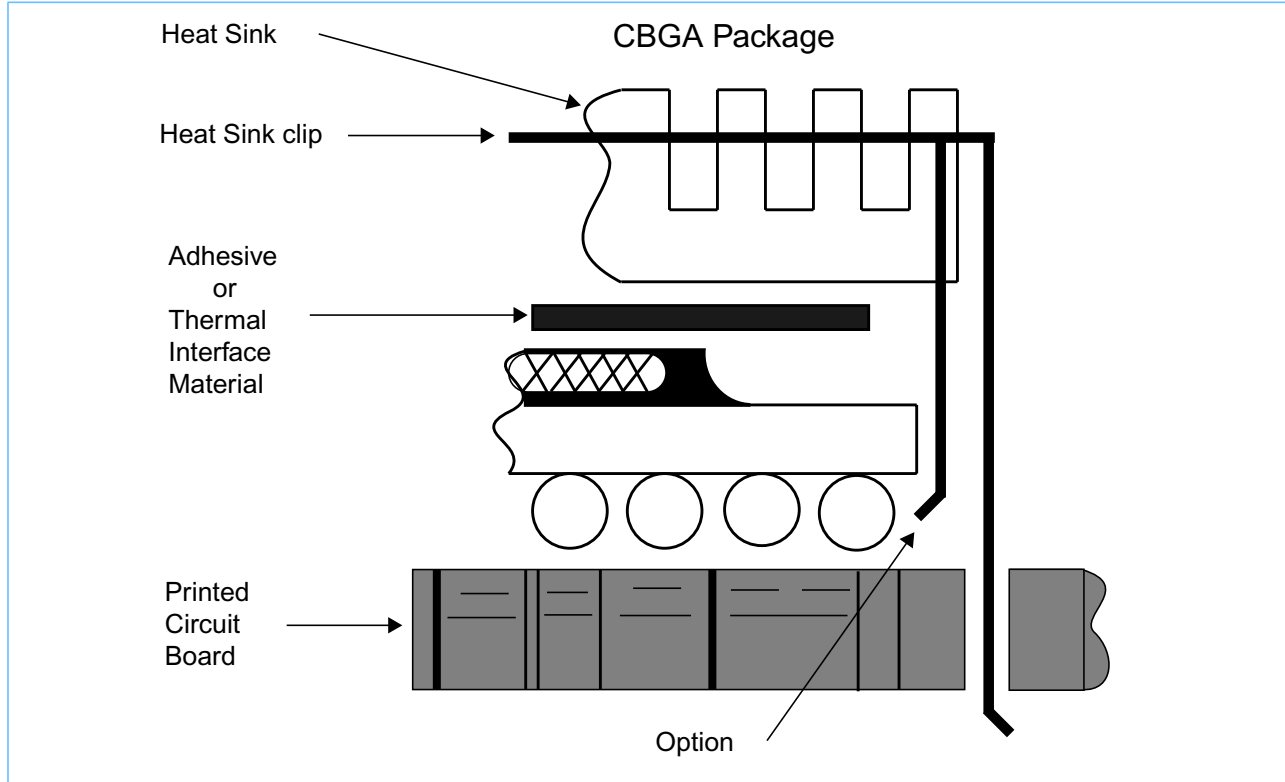


Table 5-8. Maximum Heatsink Weight Limit for the CBGA

Force	Maximum
Maximum dynamic compressive force allowed on the BGA balls	42.9 N
Maximum dynamic tensile force allowed on the BGA balls	9.05 N
Maximum dynamic compressive force allowed on the chip	14.8 N
Maximum mass of module + heatsink when heatsink is not bolted to card	50g

### 5.8.5 Thermal Assist Unit

The thermal sensor in the Thermal Assist Unit (TAU) has not been characterized to determine the basic uncalibrated accuracy. The relationship between the actual junction temperature and the temperature indicated by THRM1 and THRM2 is not well known.

IBM recommends that the TAU in these devices be calibrated before use. Calibration methods are discussed in the IBM Application Note **Calibrating the Thermal Assist Unit in the IBM25PPC750L Processors**. Although this note was written for the 750L, the calibration methods discussed in this document also apply to the 750FX.

In rare cases, the basic error of the TAU may be so large that a useful calibration cannot be achieved.

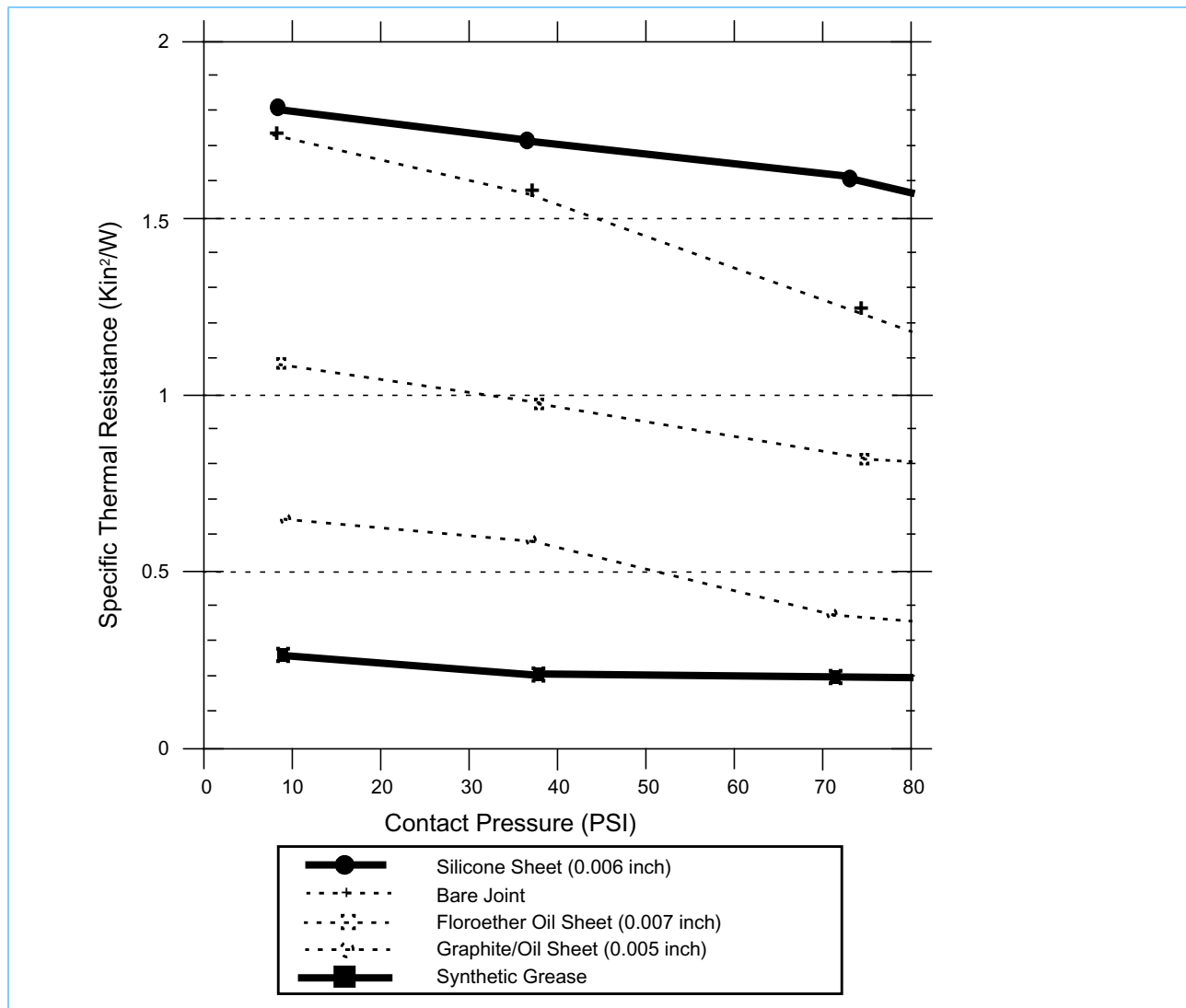


### 5.8.6 Adhesives and Thermal Interface Materials

A thermal interface material is recommended at the package die-to-heat sink interface to minimize the thermal contact resistance. For those applications where the heat sink is attached by a spring clip mechanism, *Figure 5-11* shows the thermal performance of three thin-sheet thermal-interface materials (silicon, graphite/oil, floreoether oil), a bare joint, and a joint with thermal grease, as a function of contact pressure. As shown, the performance of these thermal interface materials improves with increasing contact pressure. The use of thermal grease significantly reduces the interface thermal resistance. That is, the bare joint results in a thermal resistance approximately seven times greater than the thermal grease joint.

In this example, the heat sink is attached to the package by means of a spring clip to holes in the printed-circuit board (see *Figure 5-10 Package Exploded Cross-Sectional View with Several Heat Sink Options* on page 54). The synthetic grease offers the best thermal performance, considering the low interface pressure. The selection of any thermal interface material depends on many factors – thermal performance requirements, manufacturability, service temperature, dielectric properties, cost, and so forth.

*Figure 5-11. Thermal Performance of Select Thermal Interface Material*



### 5.8.7 Thermal Interface and Adhesive Vendors

The board designer can choose between several types of thermal interfaces. Heat sink adhesive materials should be selected based upon high conductivity, yet adequate mechanical strength to meet equipment shock/vibration requirements. A partial list of vendors that advertise thermal interface materials for PowerPC devices is shown in *Table 5-9* on page 56.

*Table 5-9. 750FX Thermal Interface and Adhesive Materials Vendors*

Company Names and Addresses for Thermal Interfaces and Adhesive Materials Vendors
Dow-Corning Corporation Dow-Corning Electronic Materials P.O. Box 0997 Midland, MI 48686-0997 (989) 496-4000 <a href="http://www.dowcorning.com/content/etronics">http://www.dowcorning.com/content/etronics</a>
Chomerics, Inc. 77 Dragon Court Woburn, MA 01888-4850 (781) 935-4850 <a href="http://www.chomerics.com">http://www.chomerics.com</a>
Thermagon, Inc. 4797 Detroit Avenue Cleveland, OH 44102-2216 (216) 939-2300 / (888) 246-9050 <a href="http://www.Thermagon.com">http://www.Thermagon.com</a>
Loctite Corporation 1001 Trout Brook Crossing Rocky Hill, CT 06067 (860) 571-5100 / (800) 562-8483 <a href="http://www.loctite.com">http://www.loctite.com</a>
AI Technology 70 Washington Road Princeton, NJ 08550-1097 (609) 799-9388 <a href="http://www.aitechnology.com">http://www.aitechnology.com</a>

### 5.8.8 Heat Sink Vendors

The board designer can choose between several types of heat sinks to place on the 750FX. A partial list of vendors that advertise heat sinks for Power PC devices is shown in *Table 5-10 A Partial Listing of 750FX Heat Sink Vendors* on page 57.

*Table 5-10. A Partial Listing of 750FX Heat Sink Vendors*

Company Names and Addresses for Heat Sink Vendors
Chip Coolers, Inc. 333 Strawberry Field Rd. Warwick, RI 02886 (800) 227-0254 <a href="http://www.chipcoolers.com">http://www.chipcoolers.com</a>
International Electronic Research Corporation (IERC) 413 North Moss Street Burbank, CA 91502 (818) 842-7277 <a href="http://www.ctscorp.com/ierc">http://www.ctscorp.com/ierc</a>
Aavid Thermalloy 80 Commercial Street Concord, NH 03301 (603) 224-9888 <a href="http://www.aavid.com">http://www.aavid.com</a> <a href="http://www.aavidthermalloy.com">http://www.aavidthermalloy.com</a>
Wakefield Thermal Solutions Inc. 33 Bridge Street Pellham, NH 03076 (603) 635-2800 <a href="http://www.wakefield.com">http://www.wakefield.com</a>





## Revision Log

Date	Description
Feb 13, 2003	Version 0.1 Initial preliminary version for general release of 750FX DD2.3.
May 16, 2003	Version 1.0 Second preliminary version which includes input/updates from designers.
May 23, 2003	Version 2.0 Third preliminary version which includes input/updates from designers.
June 3, 2003	Version 2.0 Fourth preliminary version which includes input/updates from designers.
June 5, 2003	Version 2.0 Changed from DD2.3 to DD2.X. Also included designer updates.
June 6, 2003	Version 2.0 Changed Table 3-5 Power Consumption.
June 9, 2003	Version 2.0 Removed Rev bars..

